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SECTION 1. GENERAL PART

ESD PRECAUTIONS

Electrostatically Sensitive Devices (ESD)

Some semiconductor (solid state) devices can be damaged easily by static electricity. Such components commonly are called Electrostatically Sensitive Devices (ESD). Examples of typical ESD devices are integrated circuits and some field-effect transistors and semiconductor chip components. The following techniques should be used to help reduce the incidence of component damage caused by static electricity.

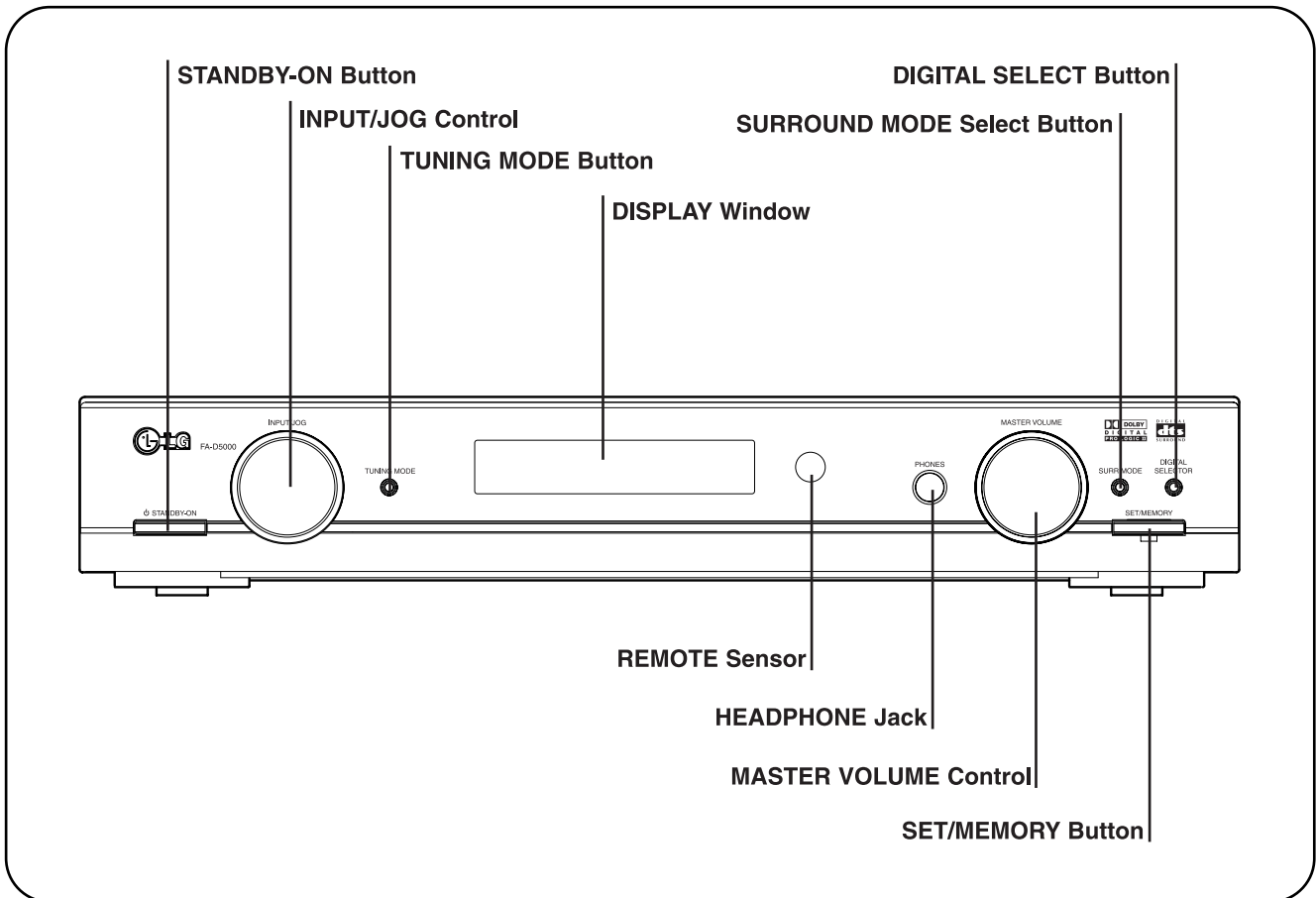
1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed for potential shock reasons prior to applying power to the unit under test.
2. After removing an electrical assembly equipped with ESD devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ESD devices.
4. Use only an anti-static solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ESD devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ESD devices.
6. Do not remove a replacement ESD device from its protective package until immediately before you are ready to install it. (Most replacement ESD devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive materials).
7. Immediately before removing the protective material from the leads of a replacement ESD device, touch the protective material to the chassis or circuit assembly into which the device will be installed.

CAUTION : BE SURE NO POWER IS APPLIED TO THE CHASSIS OR CIRCUIT, AND OBSERVE ALL OTHER SAFETY PRECAUTIONS.

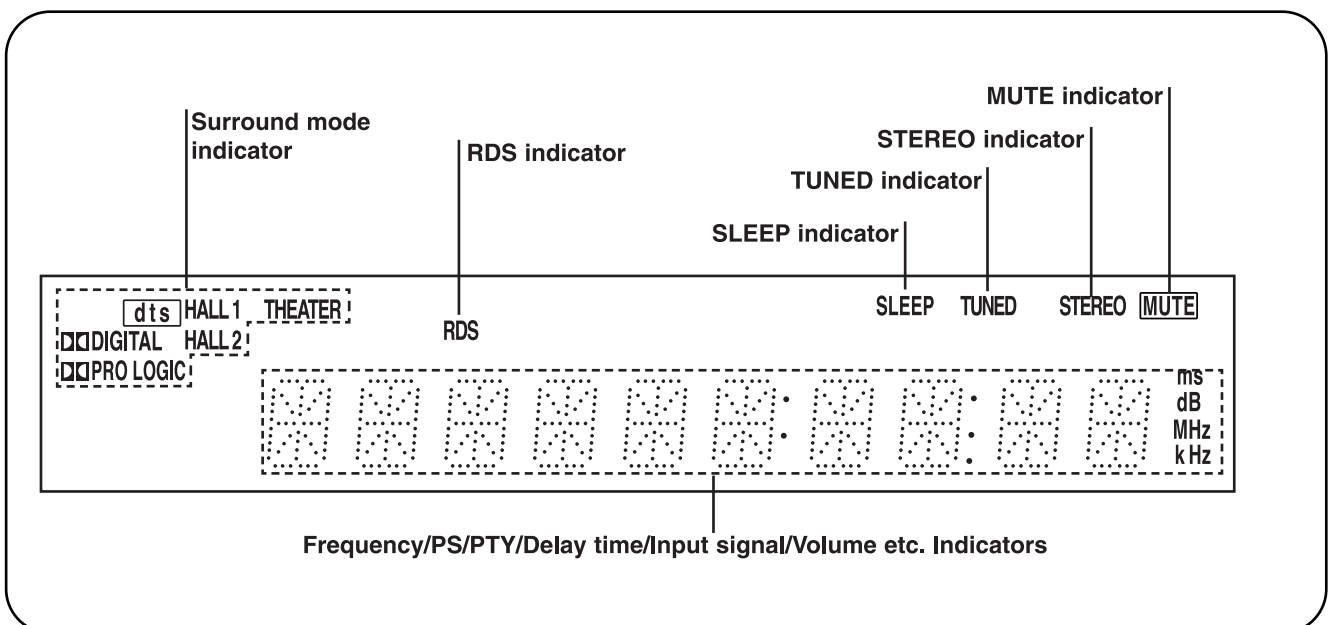
8. Minimize bodily motions when handling unpackaged replacement ESD devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ESD device).

LOCATION OF CUSTOMER CONTROLS

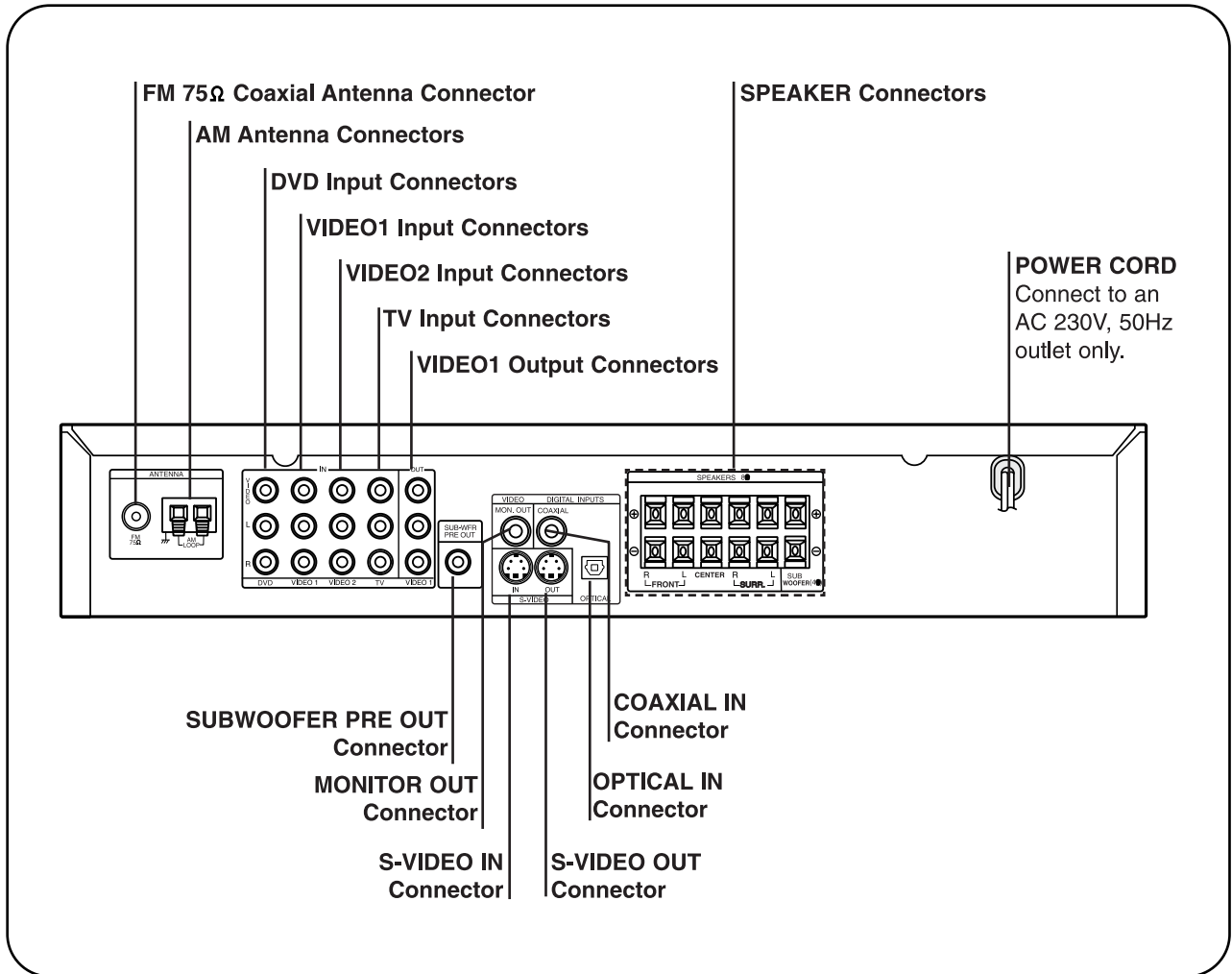
Front Panel



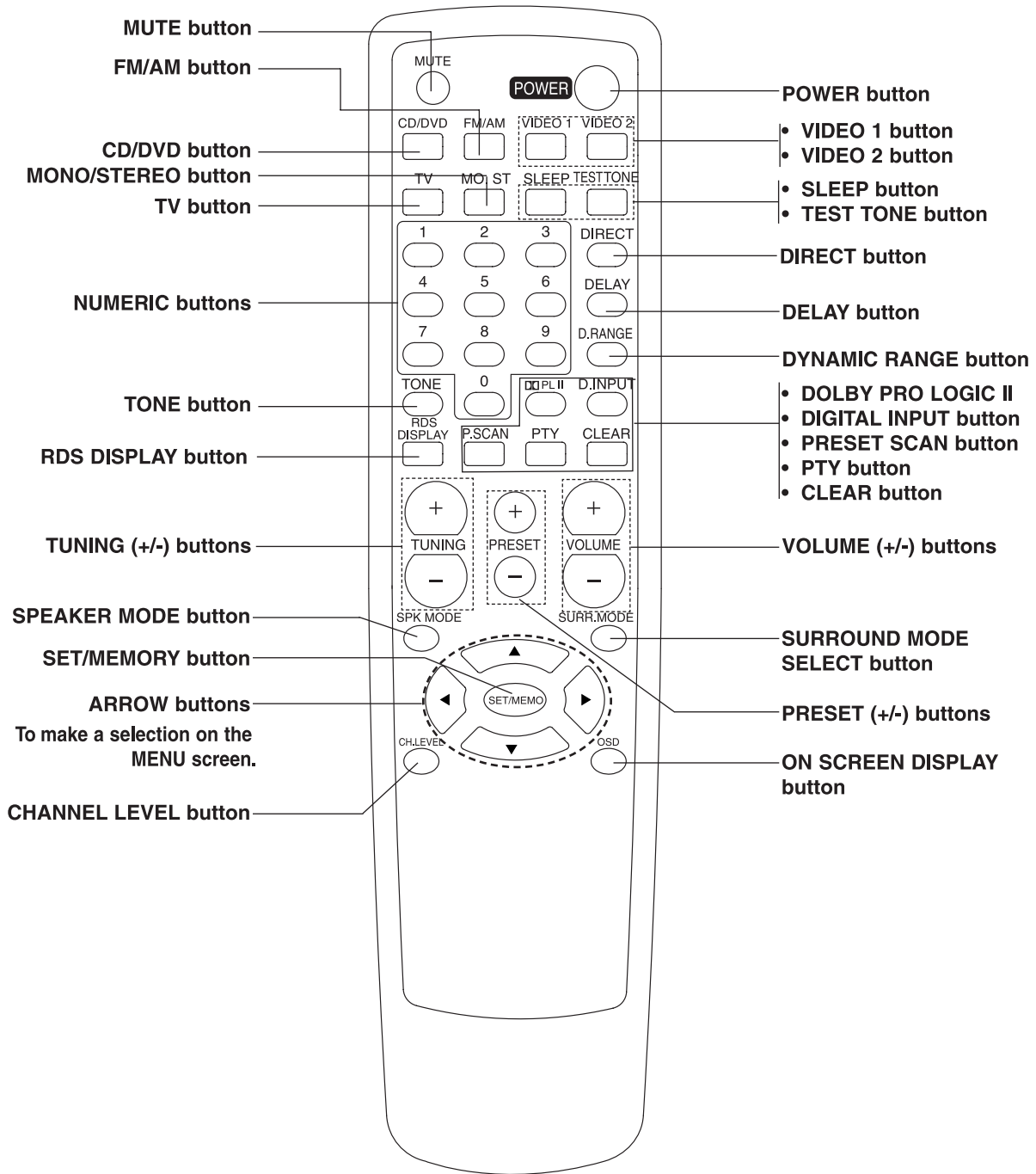
Display Window



Rear Panel



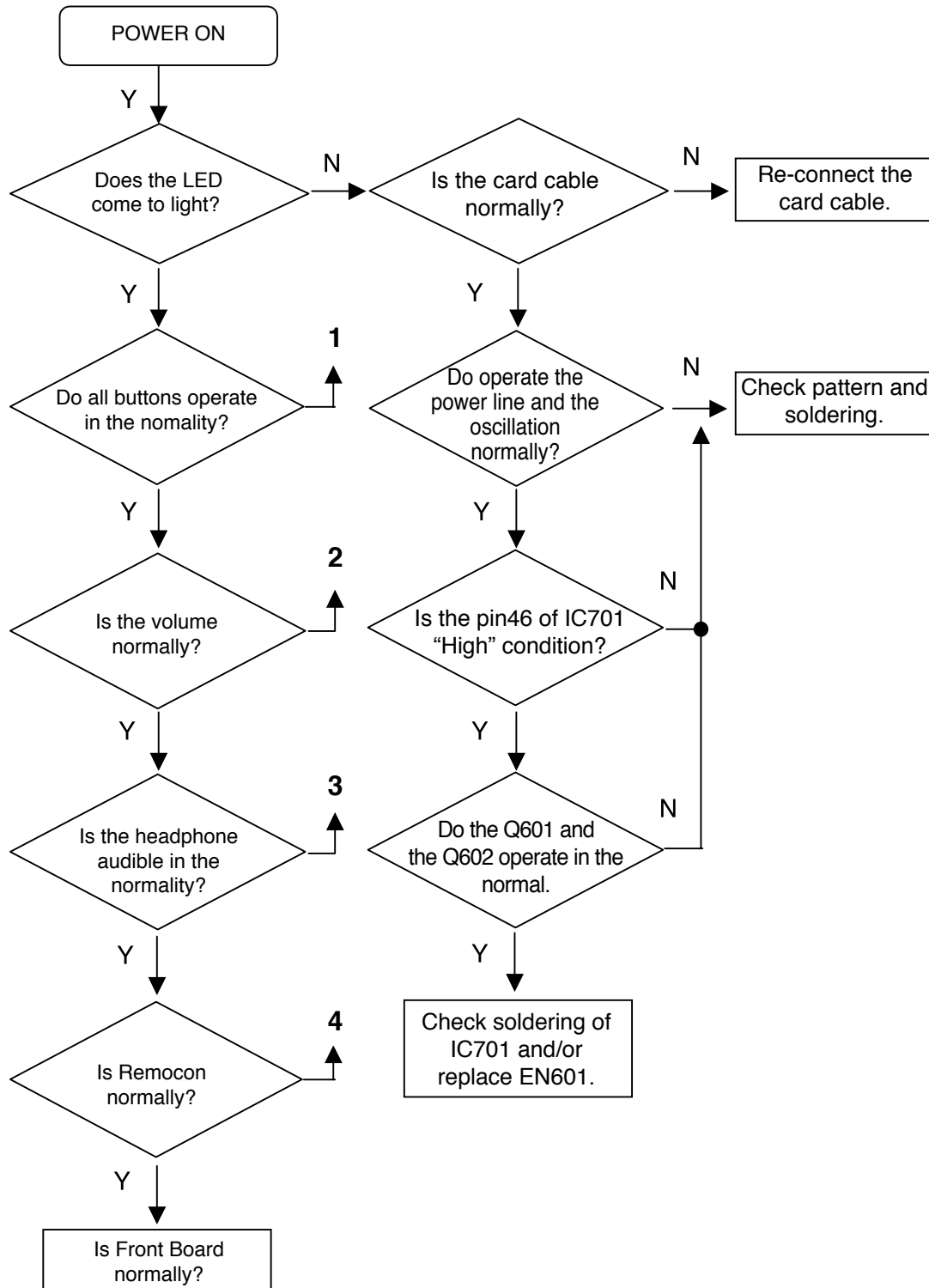
Remote Control

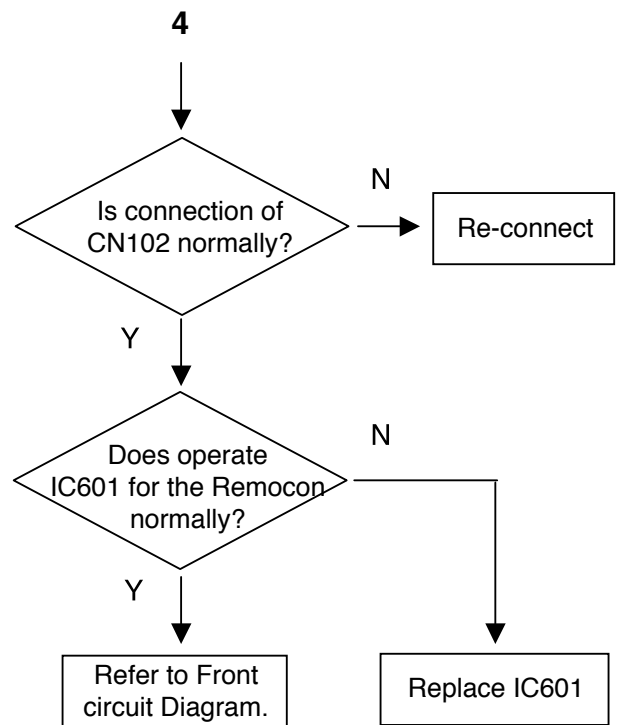
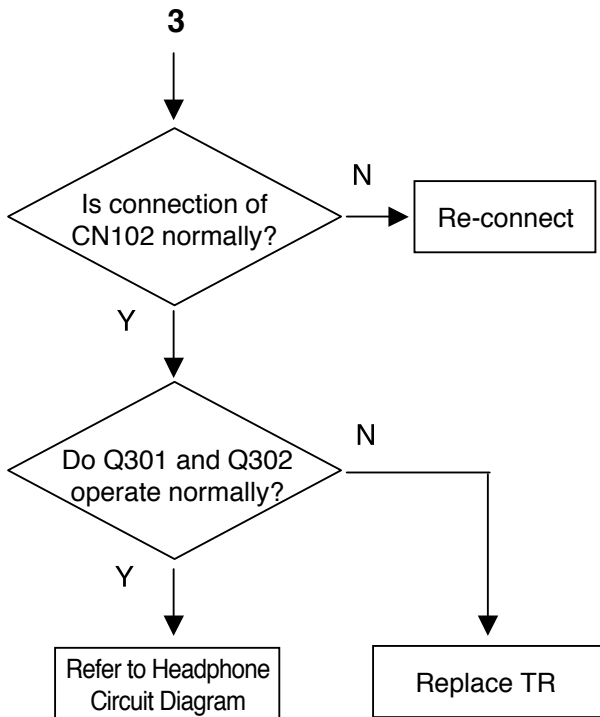
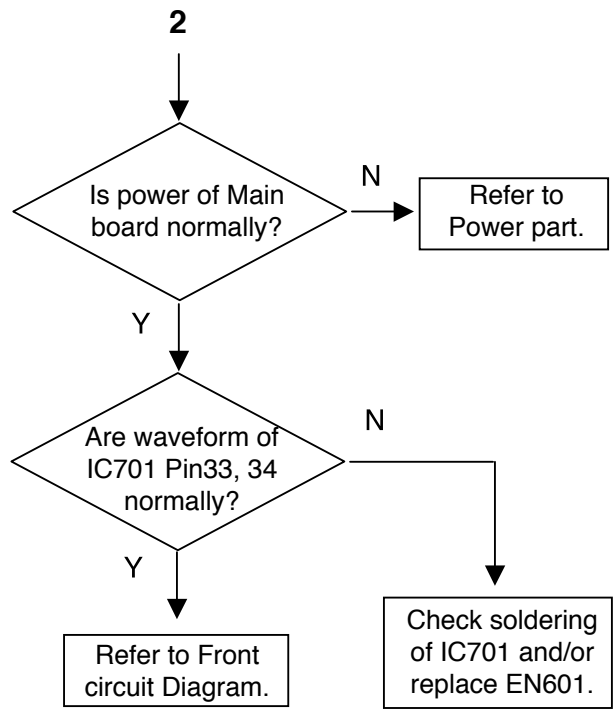
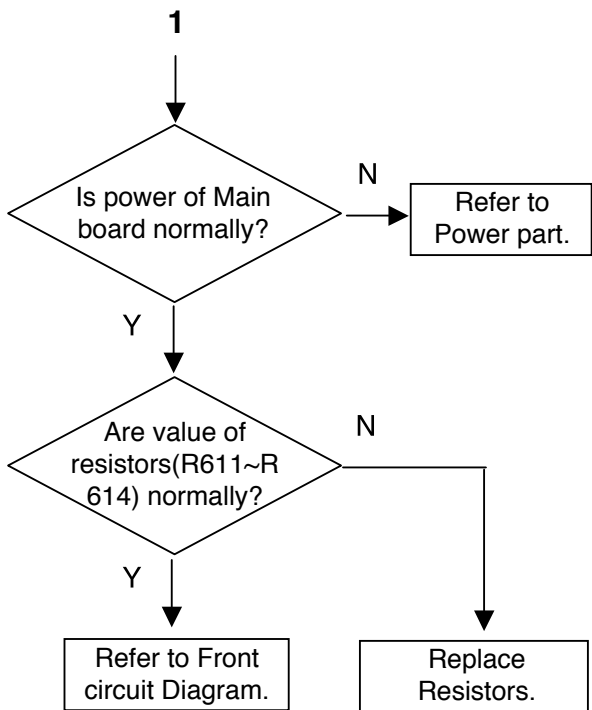


SECTION 2. AUDIO PART

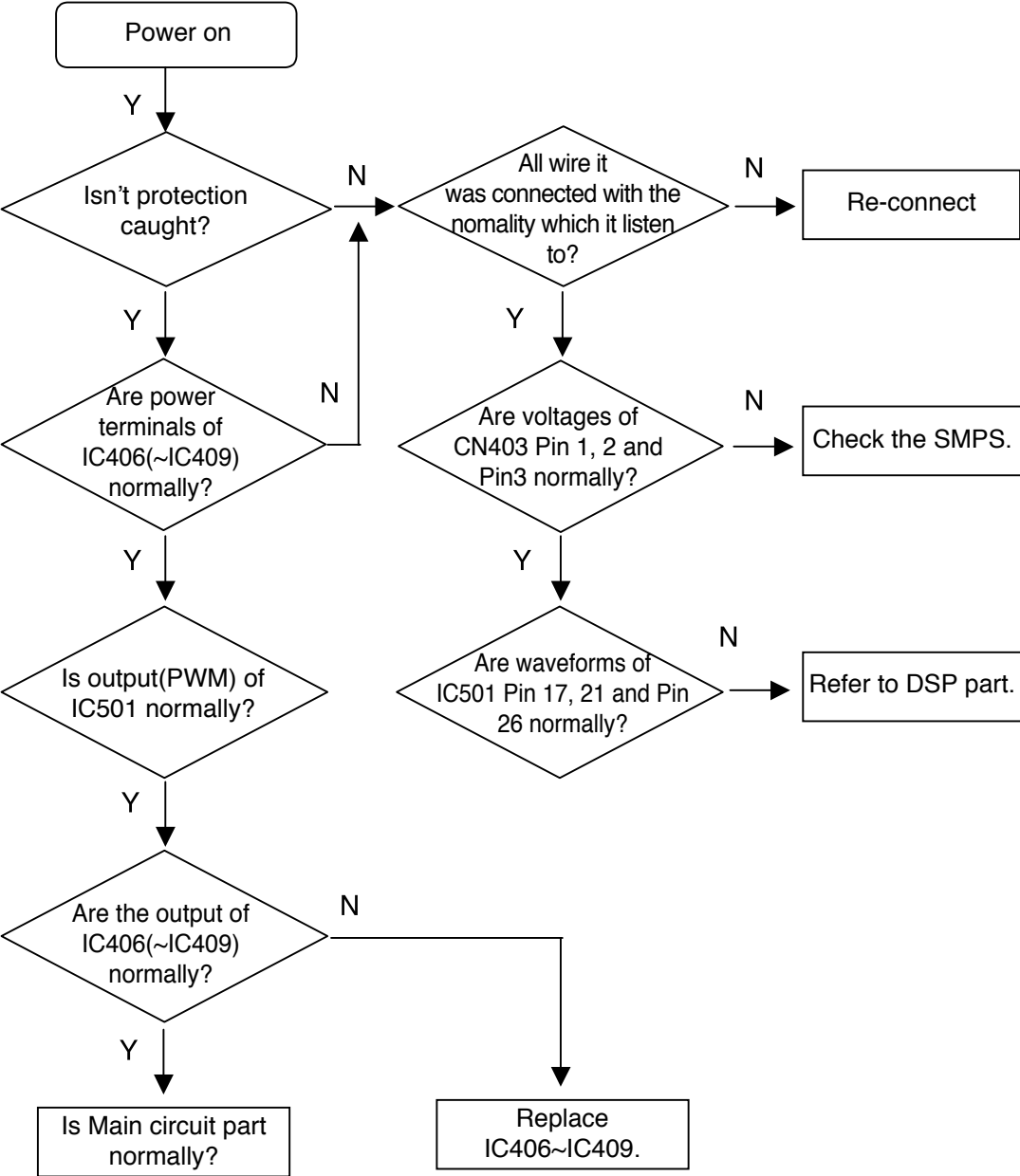
ELECTRICAL TROUBLESHOOTING GUIDE

1. FRONT Circuit

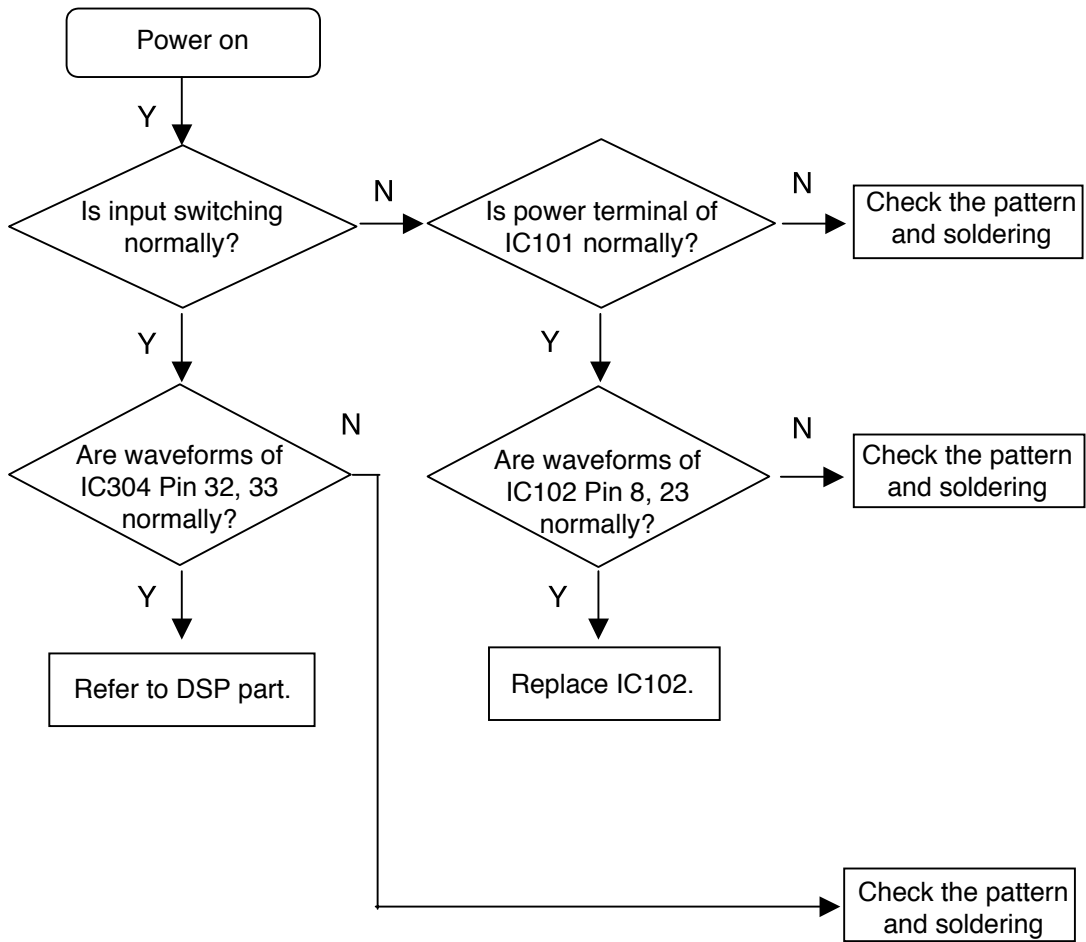




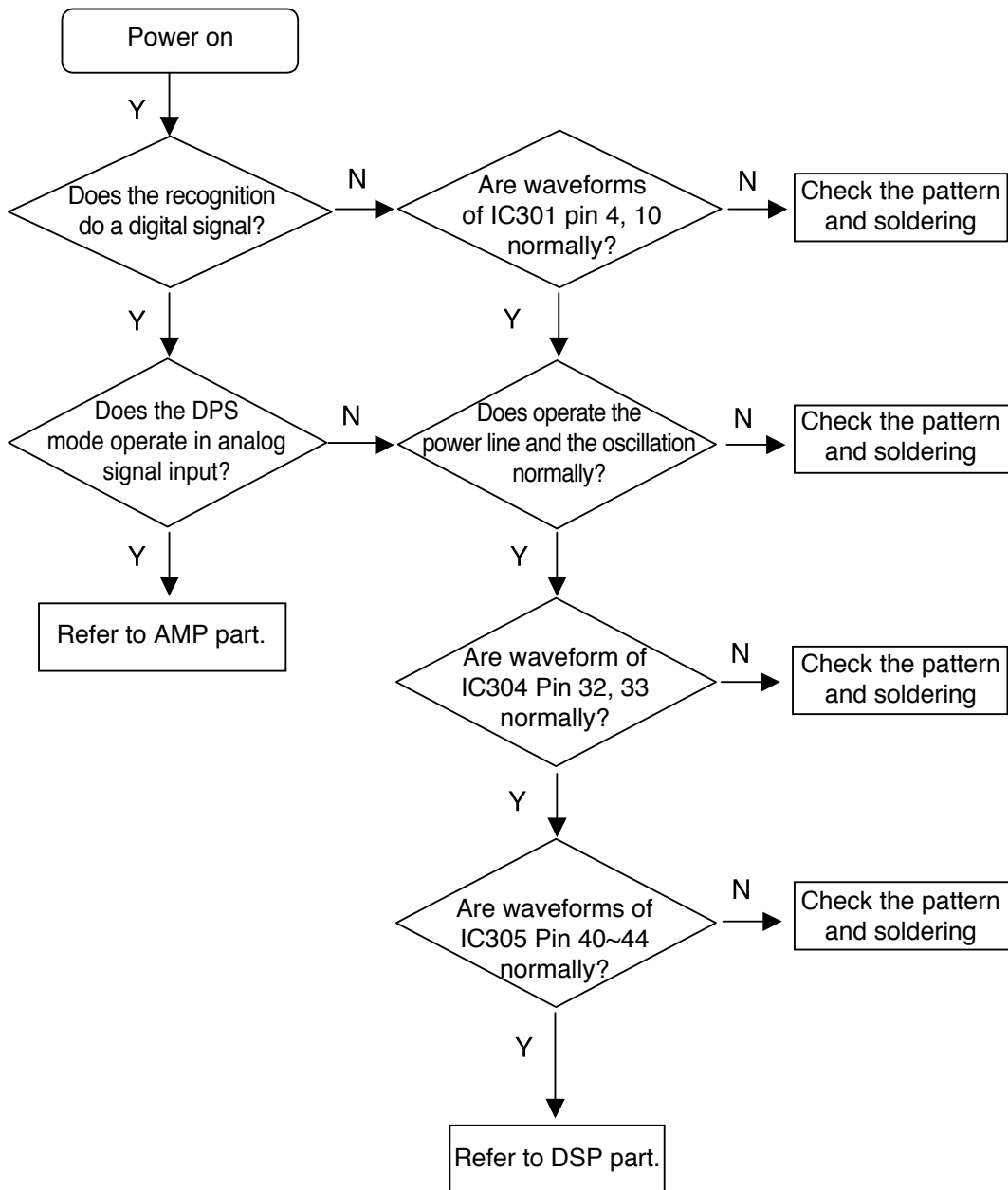
2. MAIN AMP Circuit



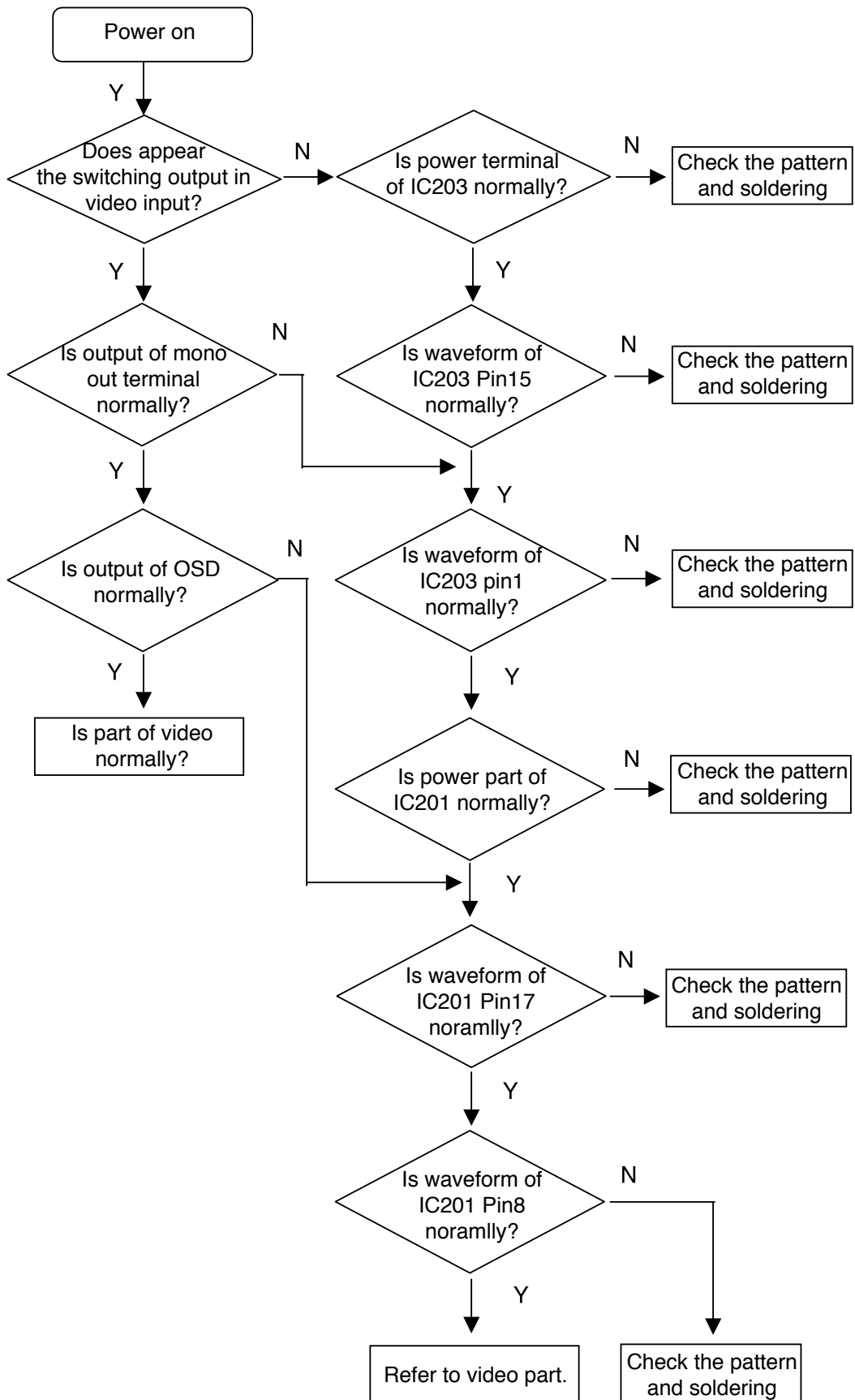
3. MAIN INPUT Circuit



4. MAIN DSP Circuit



5. MAIN VIDEO Circuit

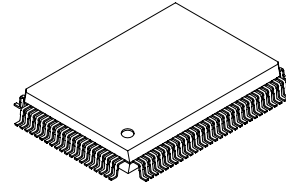


INTERNAL BLOCK DIAGRAM OF ICs

■ CXP 82860 (CMOS 8 bit Single Chip Microcomputer)

• Description

The CXP82832/82840/82852/82860 is a CMOS 8-bit single chip microcomputer integrating on a single chip an A/D converter, serial interface, timer/counter, time base timer, capture timer/counter, fluorescent display panel controller/driver, remote control reception circuit, and PWM output besides the basic configurations of 8-bit CPU, ROM, RAM, and I/O port. The CXP82832/82840/82852/82860 also provides sleep/stop function that enables lower power consumption.



100 pin QFP(Plastic)

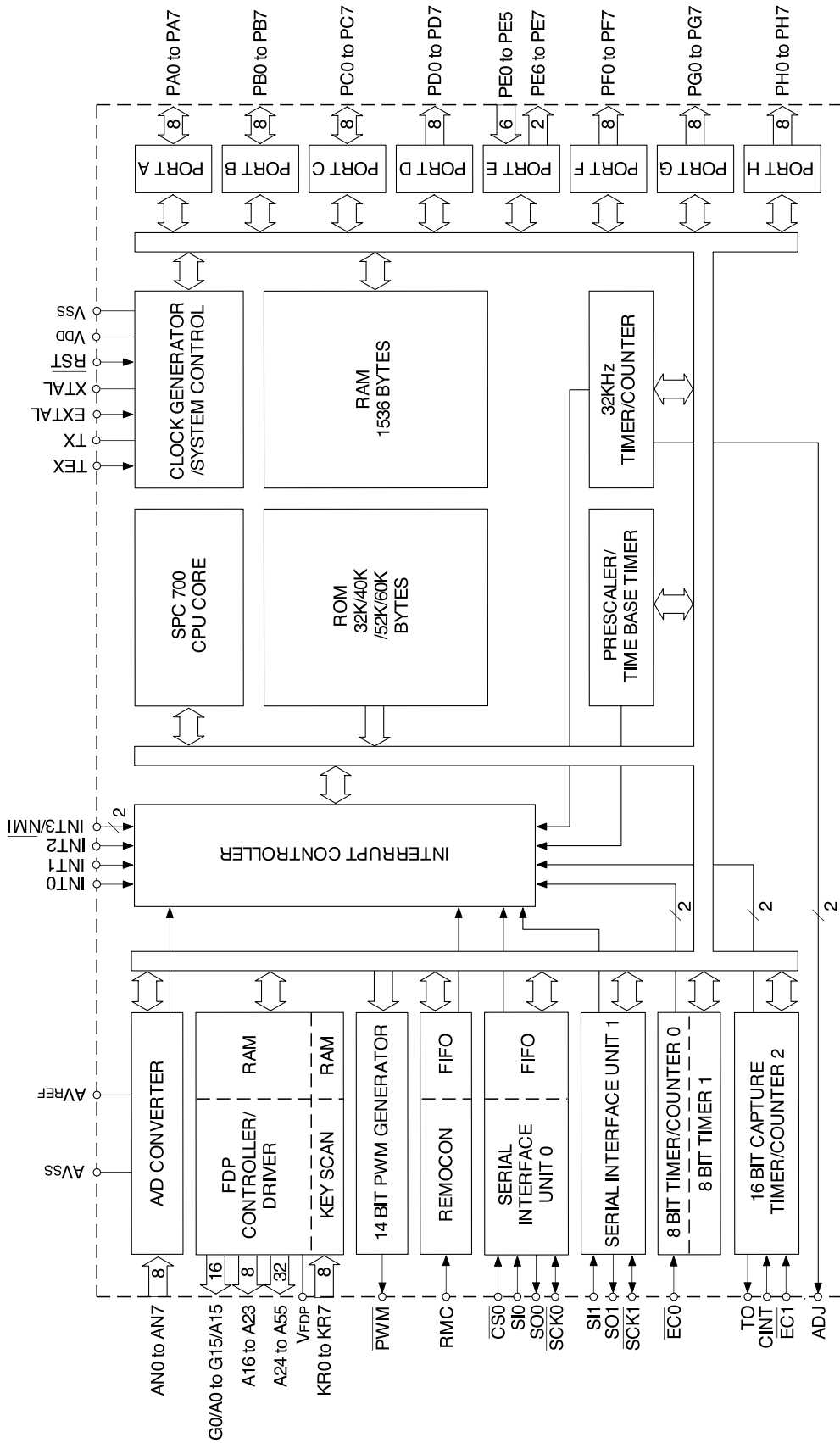
• Structure

Silicon gate CMOS IC

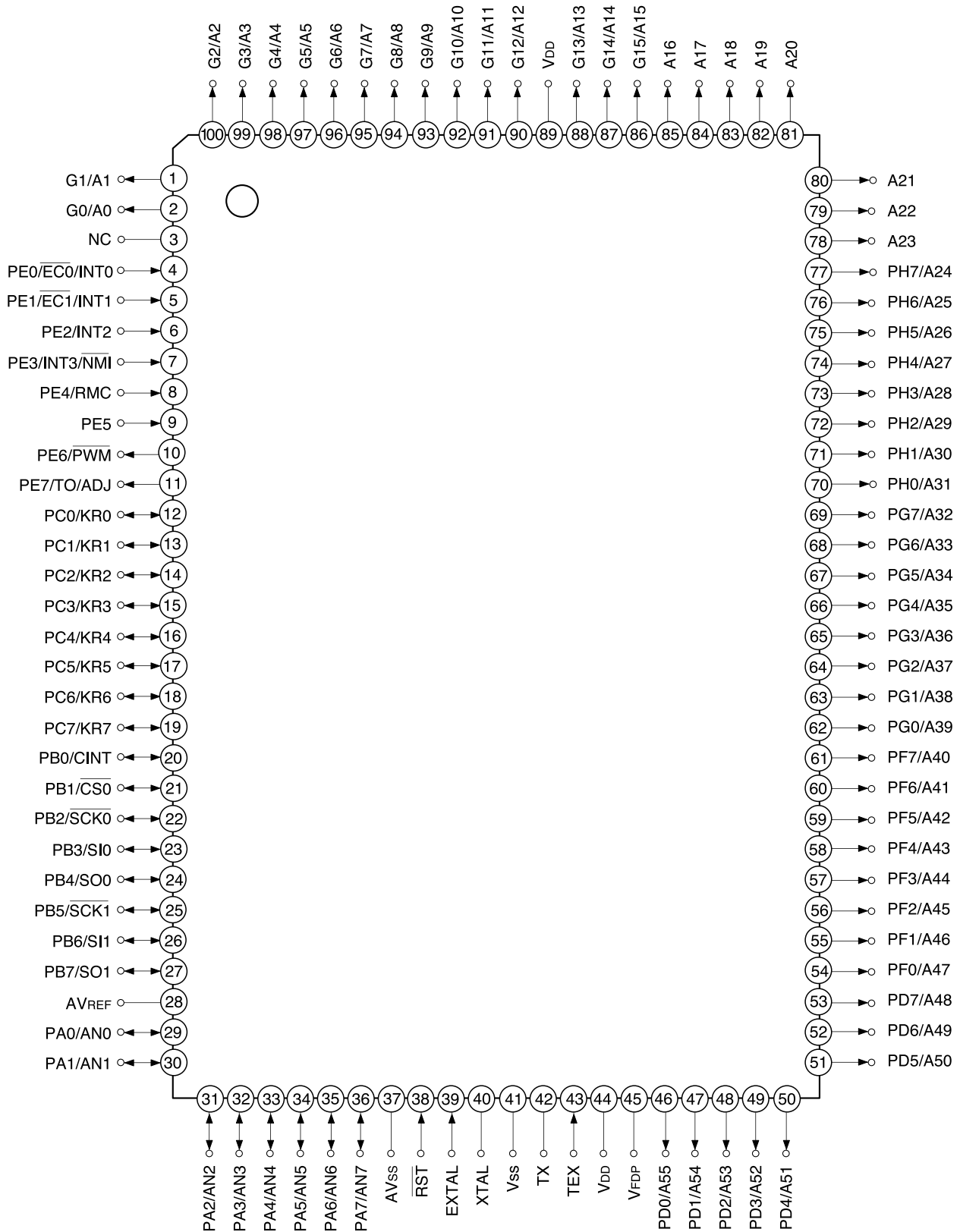
• Features

- Wide-range instruction system (213 instructions) to cover various types of data
 - 16-bit arithmetic/multiplication and division/boolean bit operation instructions
- Minimum instruction cycle
 - 400ns at 10MHz operation
 - (122μs at 32kHz operation)
- Incorporated ROM capacity
 - 32K bytes(CXP82832)
 - 40K bytes (CXP82840)
 - 52K bytes (CXP82852)
 - 60K bytes (CXP82860)
- Incorporated RAM capacity
 - 1536 bytes (including fluorescent display area)
- Peripheral functions
 - A/D converter
 - 8 bits, 8 channels, successive approximation method
 - (Conversion time of 32μs/10MHz)
 - Serial interface
 - 8-bit, 8-stage FIFO incorporated
 - (Auto transfer for 1 to 8 bytes), 1 channel
 - 8-bit clock synchronized type, 1 channel
 - Timers
 - 8-bit timer, 8-bit timer/counter, 19-bit time base timer
 - 16-bit capture timer/counter, 32kHz timer/counter
 - Fluorescent display panel controller/driver
 - Supports the universal grid fluorescent display panel.
 - High voltage drive output port of 56 pins (40V)
 - Maximum of 640 segments display possible
 - Display timing number of 1 to 20
 - Dimmer function
 - Incorporated pull-down resistor (Mask option)
 - Hardware key scan function (Maximum of 16 x 8 key matrix supportable)
 - Remote control reception circuit
 - 8-bit pulse measurement counter, 6-stage FIFO
 - PWM output
 - 14 bits, 1 channel
- Interruption
 - 16 factors, 15 vectors, multi-interruption possible
- Standby mode
 - SLEEP/STOP
- Package
 - 100-pin plastic QFP
- Piggyback/evaluation chip
 - CXP82800 100-pin ceramic QFP

• BLOCK DIAGRAM



• Pin Assignment(Top View)



Note) 1. NC (Pin 3) must be connected to VDD.

2. VDD (Pins 44 and 89) must be connected to VDD.

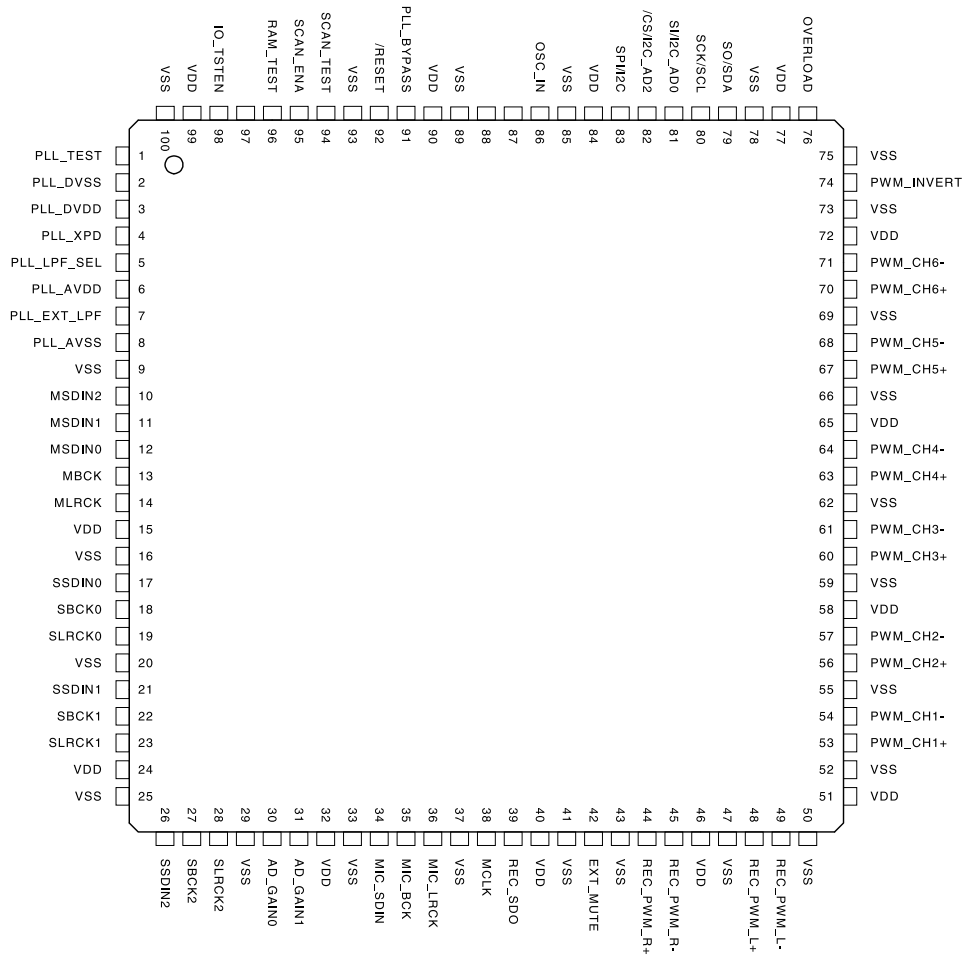
• PIN DESCRIPTION

Pin No	I/O	Function	
PA0/AN0 to PA7/AN7	I/O/ Analog input	(Port A) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of the pull-up resistor can be set through the software in a unit of 4 bits. (8pins)	Analog inputs to A/D converter. (8 pins)
PB0/CINT	I/O/Input	(Port B) 8-bit I/O port. I/O can be set in a unit of single bits. Incorporation of the pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	Capture input to 16-bit timer/counter.
PB1/ $\overline{\text{CS0}}$	I/O/Input		Chip select input for serial interface (CH0).
PB2/SCK0	I/O/I/O		Serial clock I/O (CH0).
PB3/SI0	I/O/Input		Serial data input (CH0).
PB4/SO0	I/O/Output		Serial data output (CH0).
PB5/SCK1	I/O/I/O		Serial clock I/O (CH1).
PB6/SI1	I/O/Input		Serial data input (CH1).
PB7/SO1	I/O/Output		Serial data output (CH1).
PC0/KR0 to PC7/KR7	I/O/Input	(Port C) 8-bit I/O port. I/O can be set in a unit of single bits. Can drive 12mA sync current. Incorporation of the pull-up resistor can be set through the software in a unit of 4 bits. (8 pins)	Serves as key return inputs when operating key scan with fluorescent display panel (FDP) segment signal. (8 pins)
PD0/A55 to PD7/A48	Output/Output	(Port D) 8-bit output port. (8 pins)	FDP segment signal (anode connection) outputs.
PE0/INT0/ EC0	Input/Input/Input	(Port E) 8-bit port. Lower 6 bits are for inputs; upper 2 bits are for outputs. (8 pins)	Inputs for external interruption request. (4 pins)
PE1/INT1/ EC1	Input/Input/Input		
PE2/INT2	Input/Input		Non-maskable interruption request input.
PE3/INT3/ $\overline{\text{NMI}}$	Input/Input/Input		
PE4/RMC	Input/Input		Remote control reception circuit input.
PE5	Input		
PE6/ $\overline{\text{PWM}}$	Output/Output		14-bit PWM output.
PE7/TO/ADJ	Output/Output/ Output		Output for the 16-bit timer/counter rectangular waves, and 32kHz oscillation frequency division.
PF0/A47 to PF7/A40	Output/Output	(Port F) 8-bit output port. (8pins)	FDP segment signal (anode connection) outputs.

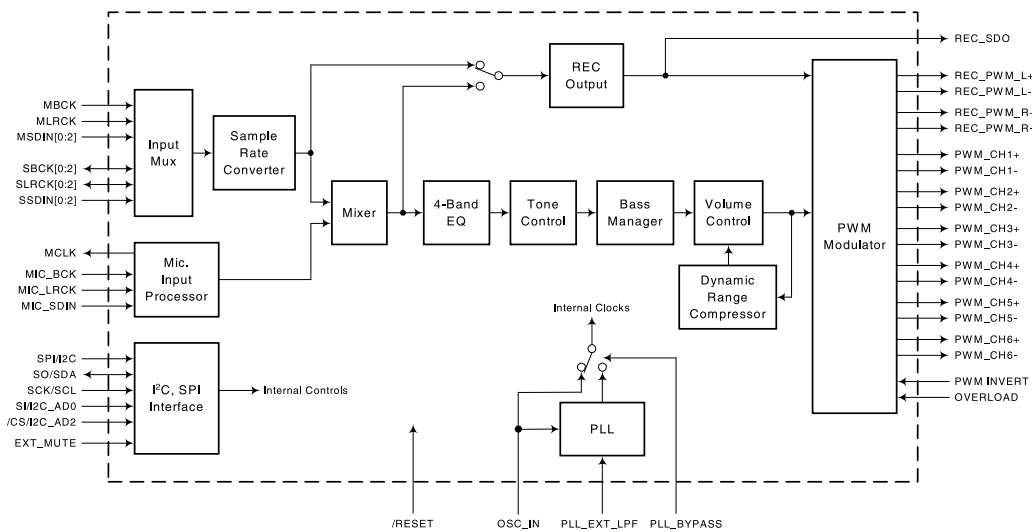
Pin No	I/O	Function	
PG0/A39 to PG7/A32	Output/Output	(Port G) 8-bit output port. (8 pins)	FDP segment signal (anode connection) outputs. (8 pins)
PH0/A31 to PH7/A24	Output/Output	(Port H) 8-bit output port. (8 pins)	FDP segment signal (anode connection) outputs. (8 pins)
A16 to A23	Output	FDP segment signal (anode connection) outputs. (8 pins)	
G0/A0 to G15/A15	Output/Output	Outputs for FDP timing signals (grid connection)/segment signals (anodeconnection). (16 pins)	
V _{FDP}		FDP voltage supply when incorporated pull-down (PD) resistor is set by mask option.	
EXTAL	Input	Crystal connectors for system clock oscillation. When the clock is supplied externally, input to EXTAL; opposite phase clock should be input to XTAL.	
XTAL	Output		
TEX	Input	Crystal connectors for 32kHz timer/counter clock oscillation. For usage as event input, input to TEX, and open TX.	
TX	Output		
$\overline{\text{RST}}$	Input	Low-level active, system reset	
NC		NC. Under normal operation, connect to V _{DD} .	
AV _{REF}	Input	Reference voltage input for A/D converter.	
AV _{SS}		A/D converter GND.	
V _{DD}		V _{CC} supply.	
V _{SS}		GND.	

PS9702B (6ch, 24bit, 192kHz Digital Audio Processor for Full Digital Amplifier)

PIN CONFIGURATION

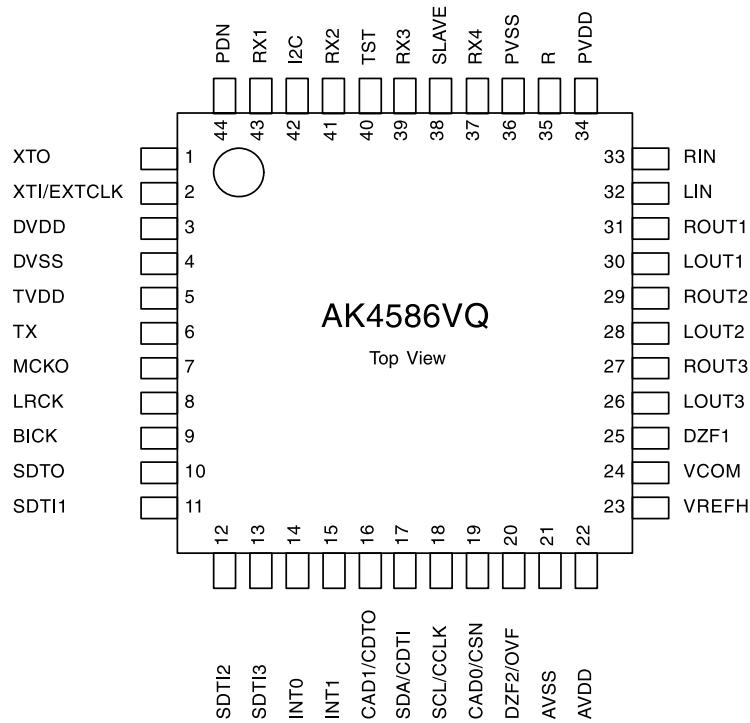


BLOCK DIAGRAM

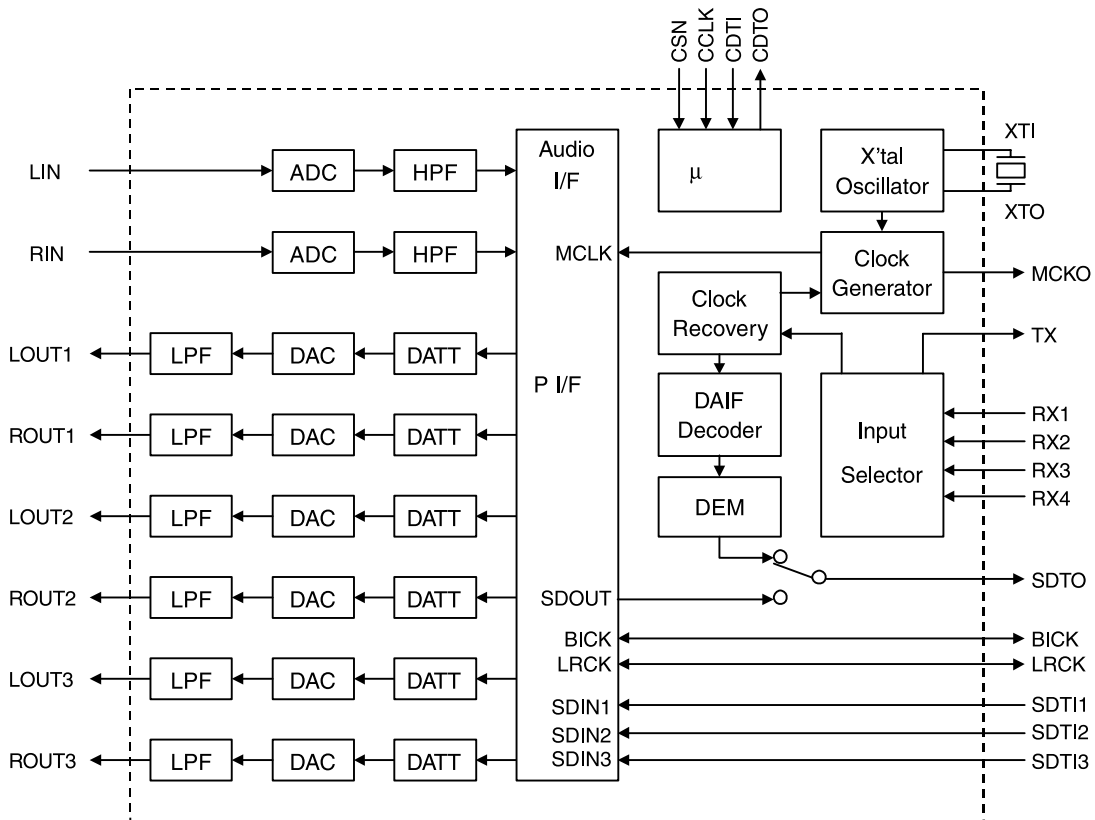


■ Ak4586 (Multi-channel Audio CODEC with DIR)

• PIN CONFIGURATION

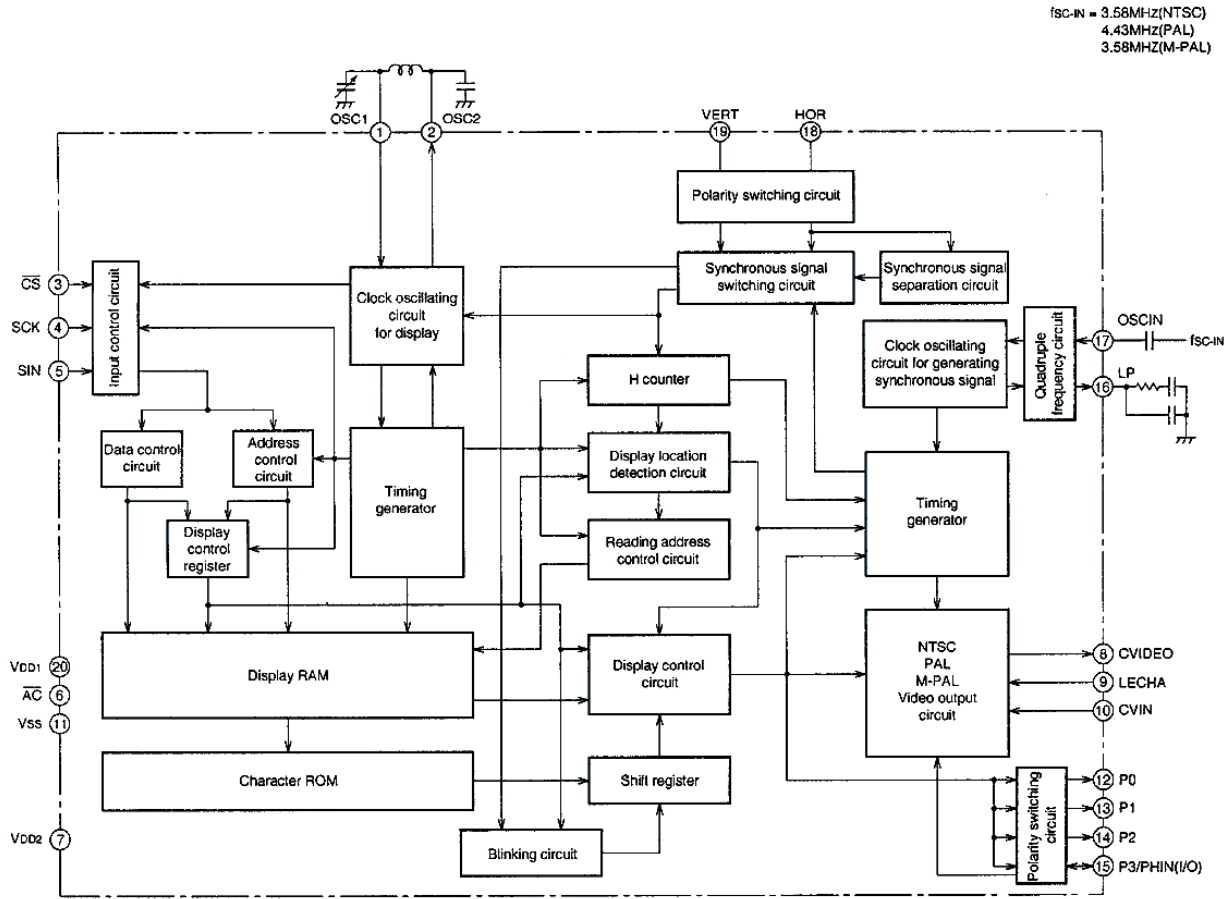


• BLOCK DIAGRAM

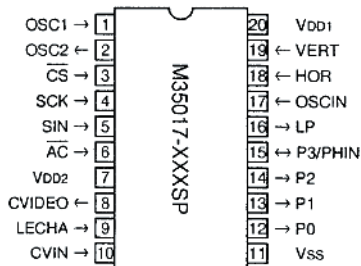


■ M35017 (Screen Character and Pattern Display Controllers)

• BLOCK DIAGRAM



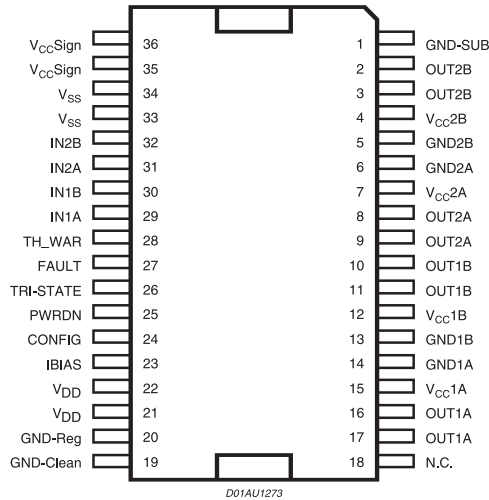
• PIN CONFIGURATION



Outline 20P4B

■ STA505 (40V 3.5A QUAD Power Half Bridge)

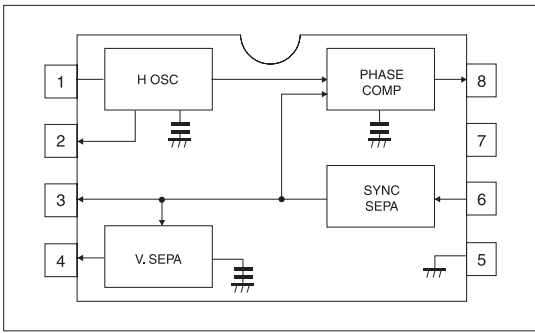
• PIN CONFIGURATION



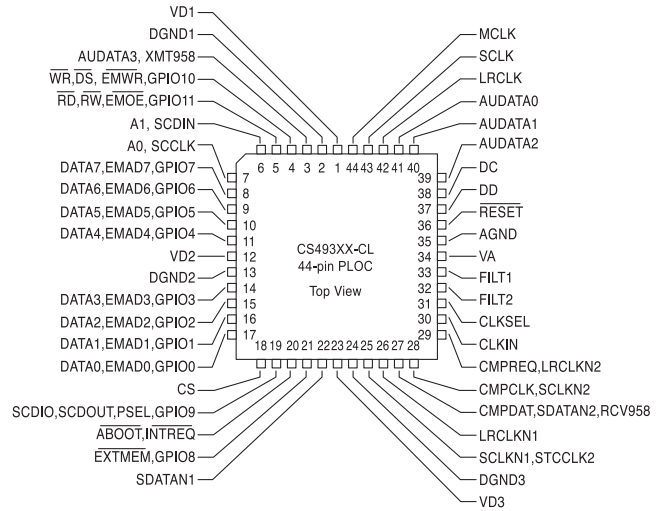
• PIN DESCRIPTION

N5	Pin	Description
1	GND-SUB	Substrate ground
35 ; 36	V _{cc} Sign	Signal Positive supply
15	V _{cc} 1A	Positive supply
12	V _{cc} 1B	Positive supply
7	V _{cc} 2A	Positive supply
4	V _{cc} 2B	Positive supply
14	GND1A	Negative Supply
13	GND1B	Negative Supply
6	GND2A	Negative Supply
5	GND2B	Negative Supply
16 ; 17	OUT1A	Output half bridge 1A
10 ; 11	OUT1B	Output half bridge 1B
8 ; 9	OUT2A	Output half bridge 2A
2 ; 3	OUT2B	Output half bridge 2B
29	IN1A	Input of half bridge 1A
30	IN1B	Input of half bridge 1B
31	IN2A	Input of half bridge 2A
32	IN2B	Input of half bridge 2B
21 ; 22	V _{dd}	5V Regulator referred to ground
33 ; 34	V _{ss}	5V Regulator referred to +V _{cc}
25	PWRDN	Stand-by pin
26	TRI-STATE	Hi-Z pin
27	FAULT	Fault pin advisor
24	CONFIG	Configuration pin
28	TH-WAR	Thermal warning advisor
19	GND-clean	Logical ground
23	IBIAS	High logical state setting voltage
18	NC	Not connected
20	GND-Reg	Ground for regulator V _{dd}

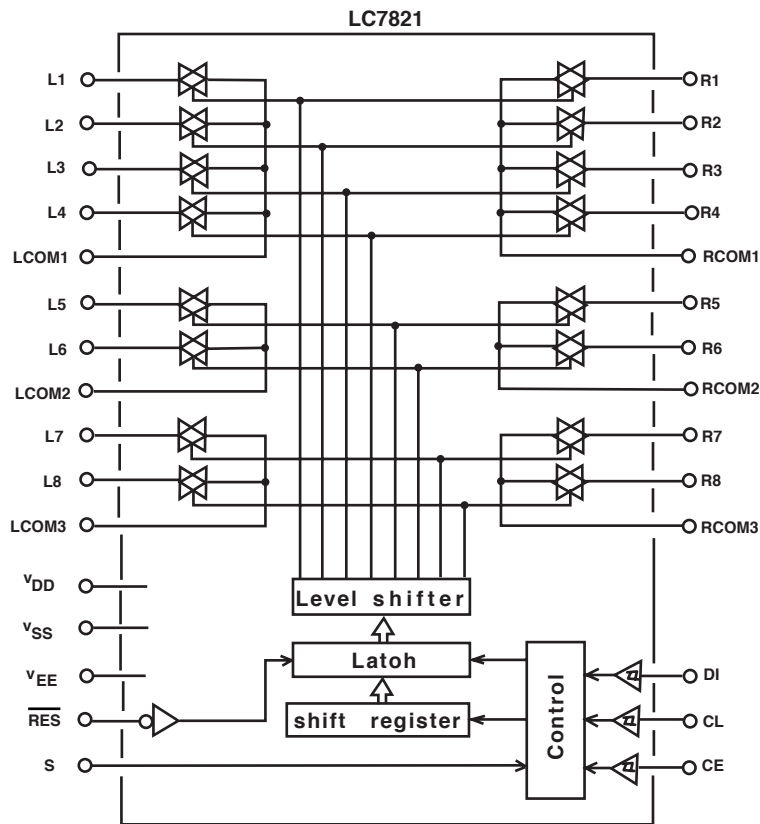
■ BA7046



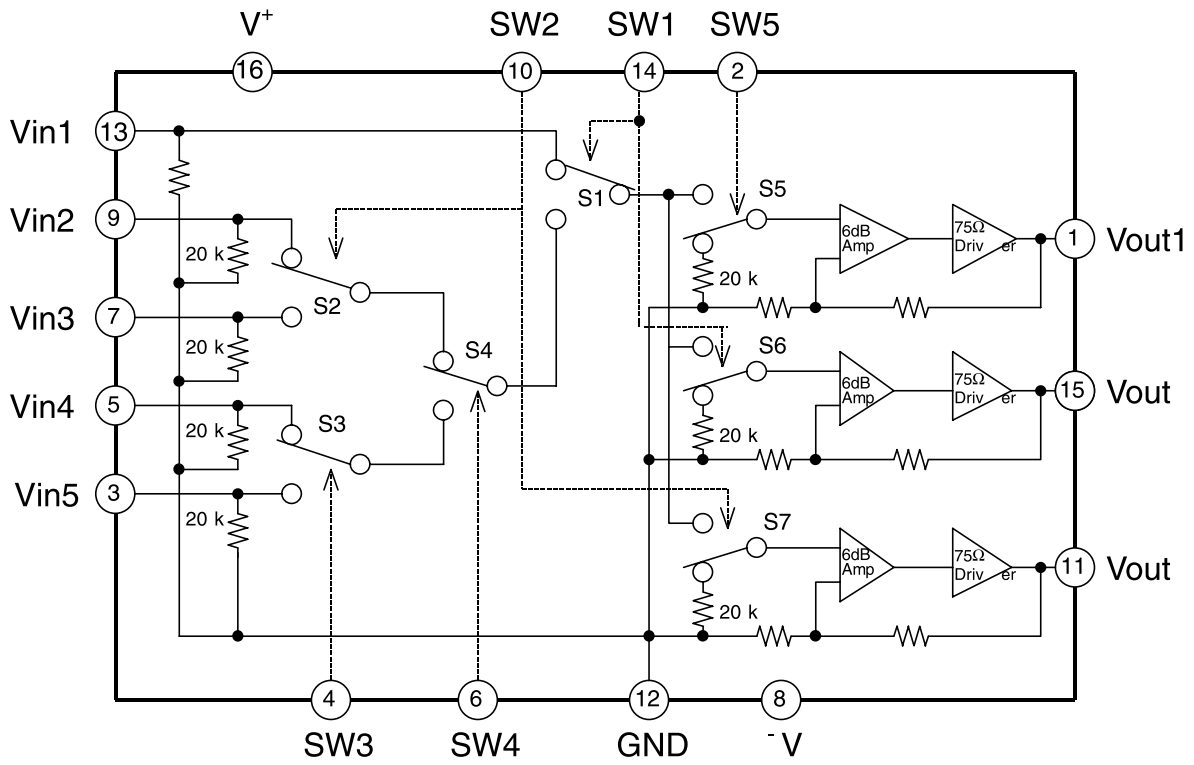
■ CS49326



■ LC7821



■ NJM2296



IC, TR VOLTAGE SHEET

• IC 101

PIN NO.	VEE(12)	DI(14)	VDD(19)
VOLT	-12V	4.5V	12.6V

• IC 103

PIN NO.	VEE(4)	VDD(7)
VOLT	-12V	12.5V

• IC 202

PIN NO.	VDD(7)	GND(5)
VOLT	4.5V	0

• IC 701

PIN NO.	VDD(44)	VDD(89)
VOLT	4.75V	4.75V

• IC 301

PIN NO.	VDD(14)	GND(7)
VOLT	3.3V	0

• IC 305

PIN NO.	VD1(1)	DGND1(2)	VD2(12)	DGND(13)	VD3(23)	DGND3(24)
VOLT	2.5 V	0	2.54V	0	2.54V	0

• IC 306

PIN NO.	GND(10)	VDD(20)
VOLT	0	3.3V

• IC 308

PIN NO.	VEE(4)	VDD(7)
VOLT	-11.3V	11.8V

• IC 102

PIN NO.	VEE(4)	VDD(7)
VOLT	-11.3V	11.8V

• IC 102

PIN NO.	VDD2(7)	VDD1(20)
VOLT	4.6V	4.6V

• IC 203

PIN NO.	VEE(8)	VDD(16)	GND(12)
VOLT	-5V	4.7V	0

• IC 303

PIN NO.	GND(10)	VDD(20)
VOLT	0	3.3V

• IC 304

PIN NO.	DVDD(3)	AVDD(22)	PVDD(34)
VOLT	4.66V	4.66V	4.66V

• IC 307

PIN NO.	VEE(4)	VDD(7)
VOLT	-12V	12.5V

• IC 309

PIN NO.	VEE(4)	VDD(7)
VOLT	-11.3V	11.8V

• IC 301

PIN NO.	VEE(4)	VDD(7)
VOLT	-11.3V	11.8V

• IC 501

PIN NO.	VDD(15)	VDD(32)	VDD(40)	VDD(46)	VDD(58)
VOLT	3.3V	3.3V	3.3V	3.3V	3.3V
PIN NO.	VDD(65)	VDD(72)	VDD(77)	VDD(84)	VDD(90)
VOLT	3.3V	3.3V	3.3V	3.3V	3.3V

• IC 406

PIN NO.	GND(19)	VDD(21,22)
VOLT	0	4.8V

• IC 407

PIN NO.	GND	VDD(21,22)
VOLT	0	4.9V

• IC 408

PIN NO.	GND	VDD(21,22)
VOLT	0	4.9V

• IC 409

PIN NO.	GND	VDD(21,22)
VOLT	0	4.9V

• Q 201

PIN NO.	E	C	B
VOLT	2.2V	4.6V	2.1V

• Q 202

PIN NO.	E	C	B
VOLT	1.4V	4.5V	2.2V

• Q 203

PIN NO.	E	C	B
VOLT	2V	0V	1.2V

• Q 710

PIN NO.	E	C	B
VOLT	4.6V	4.0V	5.4V

• Q 711

PIN NO.	E	C	B
VOLT	4.6V	4.5V	4.0V

• Q 301

PIN NO.	E	C	B
VOLT	0	0	4.4V

• Q 301

PIN NO.	E	C	B
VOLT	1.3V	1.2V	0

• Q 303

PIN NO.	E	C	B
VOLT	0	0	0.7V

• Q 304

PIN NO.	E	C	B
VOLT	0	0	0.7V

• Q 501

PIN NO.	E	C	B
VOLT	0	4.6V	3.3V

• Q 425

PIN NO.	E	C	B
VOLT	0	0	4.4V

• Q 454

PIN NO.	E	C	B
VOLT	3.3V	3.3V	2.6V

• Q 401

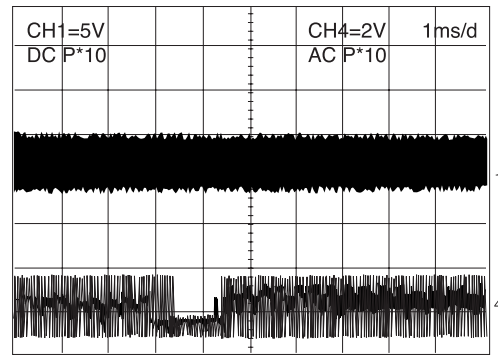
PIN NO.	E	C	B
VOLT	0	0	2.9V

• Q 201

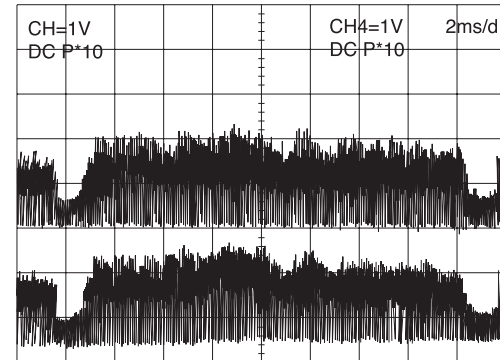
PIN NO.	E	C	B
VOLT	0	0	3.3V

WAVEFORMS OF MAJOR CHECK POINT

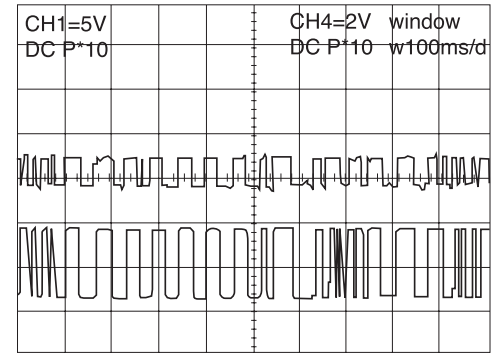
IC201 PIN 1, 8



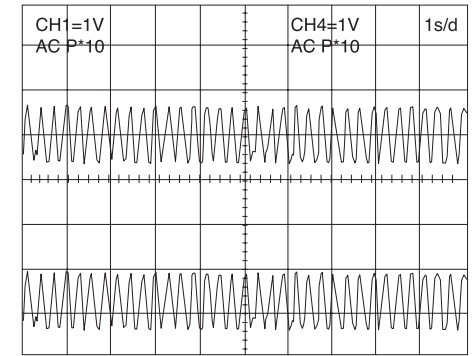
IC203 PIN 1, 15



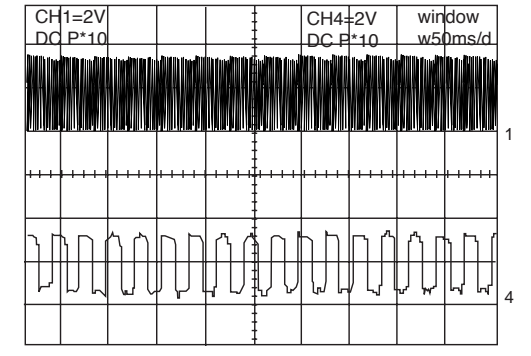
IC301 PIN 4, 10



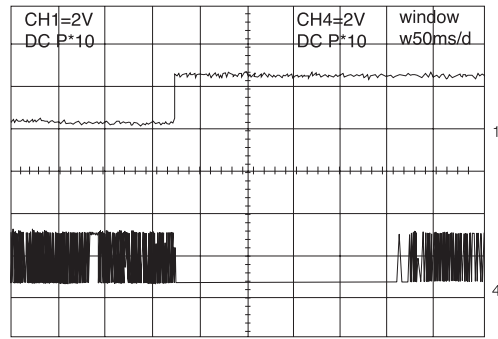
IC304 PIN 32, 33



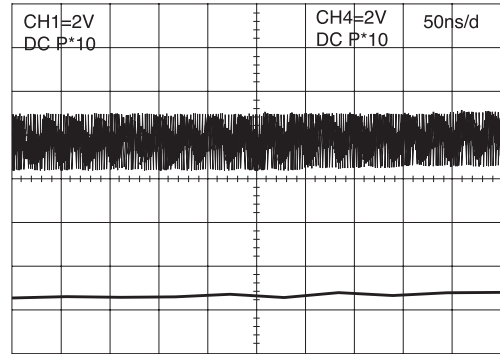
IC304 PIN 44, 43



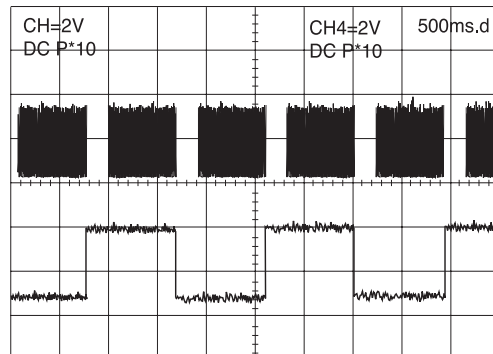
IC305 PIN 42, 41



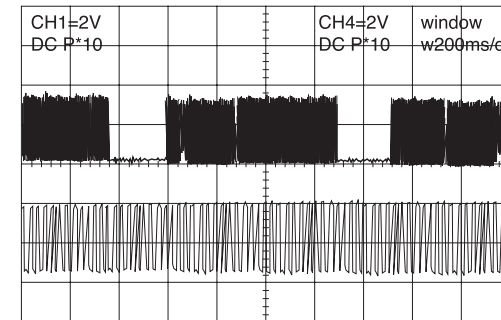
IC501 PIN 8



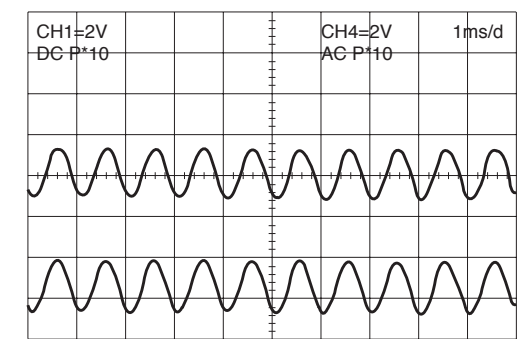
IC501 PIN 17, 23



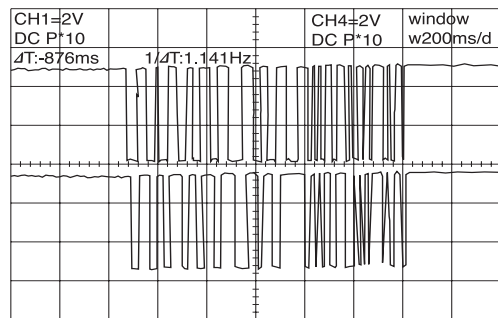
IC501 PIN 21, 22



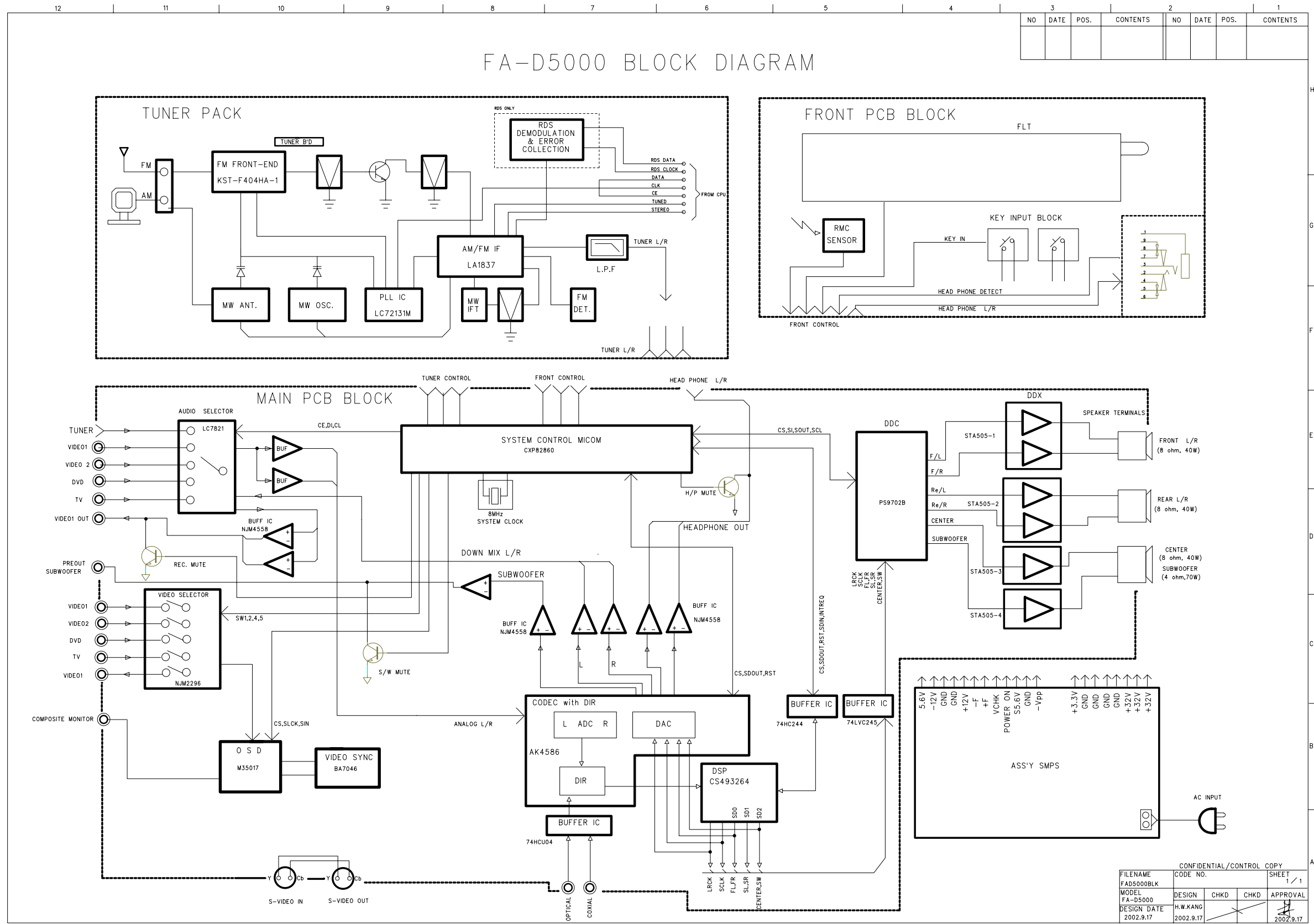
IC701 PIN8, 23



IC707 PIN33, 34



BLOCK DIAGRAM



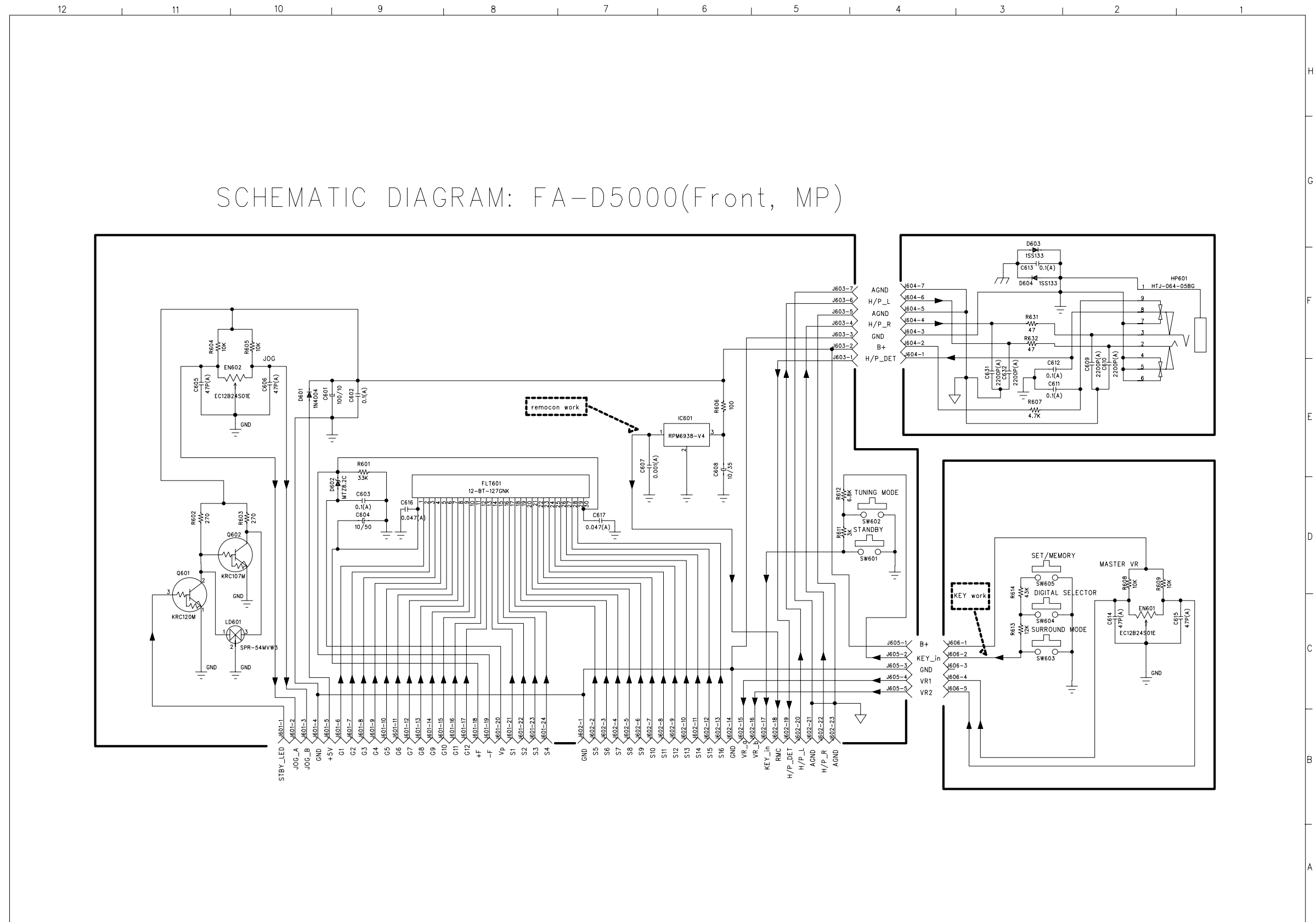
NO	DATE	POS.	CONTENTS	NO	DATE	POS.	CONTENTS

CONFIDENTIAL/CONTROL COPY			
FILENAME	CODE NO.	SHEET	
FAD5000BLK		1	1
MODEL	DESIGN	CHKD	APPROVAL
FA-D5000	H.W.KANG		
DESIGN DATE	2002.9.17		2002.9.17

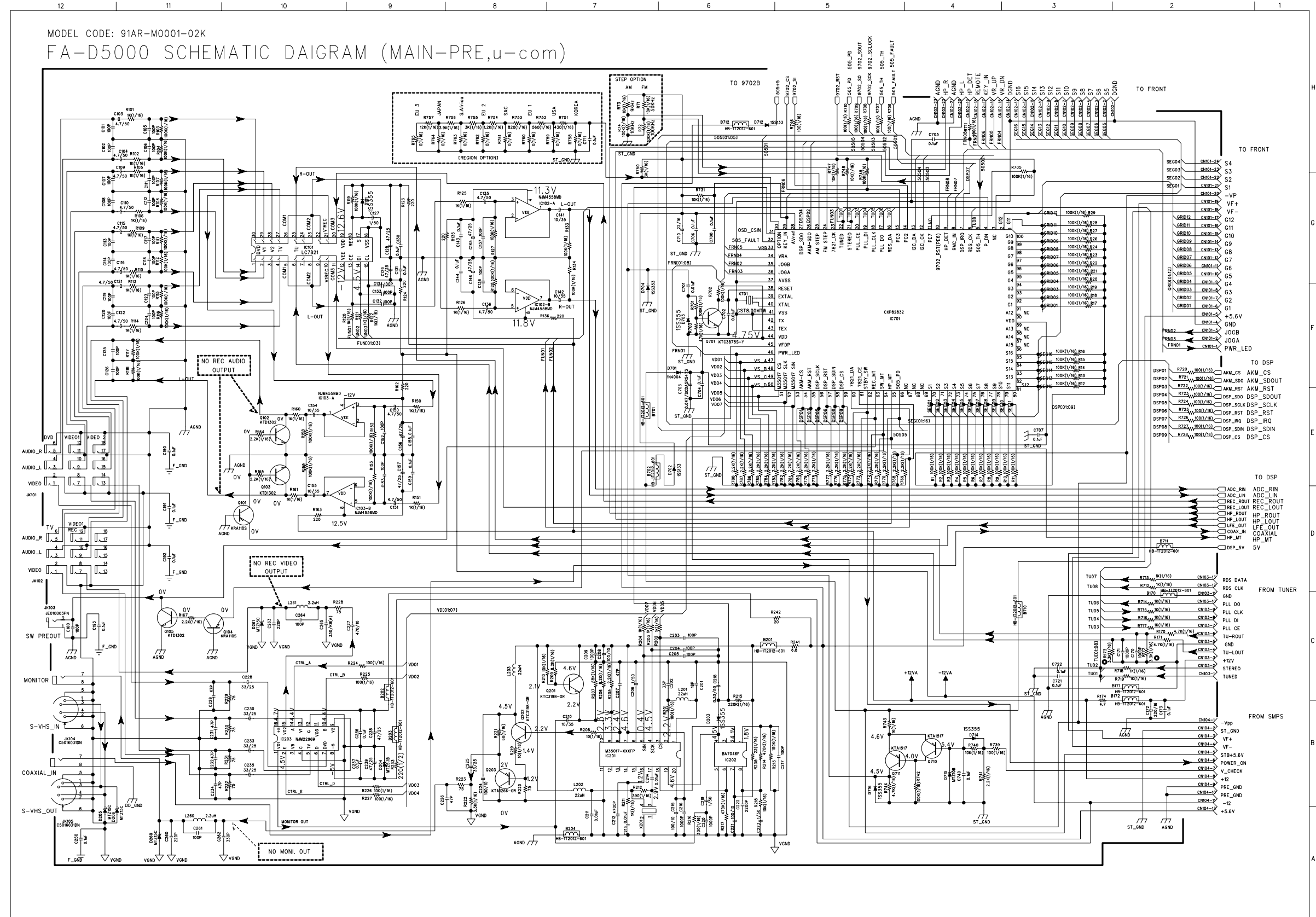
TAE KWANG INDUSTRIAL CO.,LTD

SHEMATIC DIAGRAMS

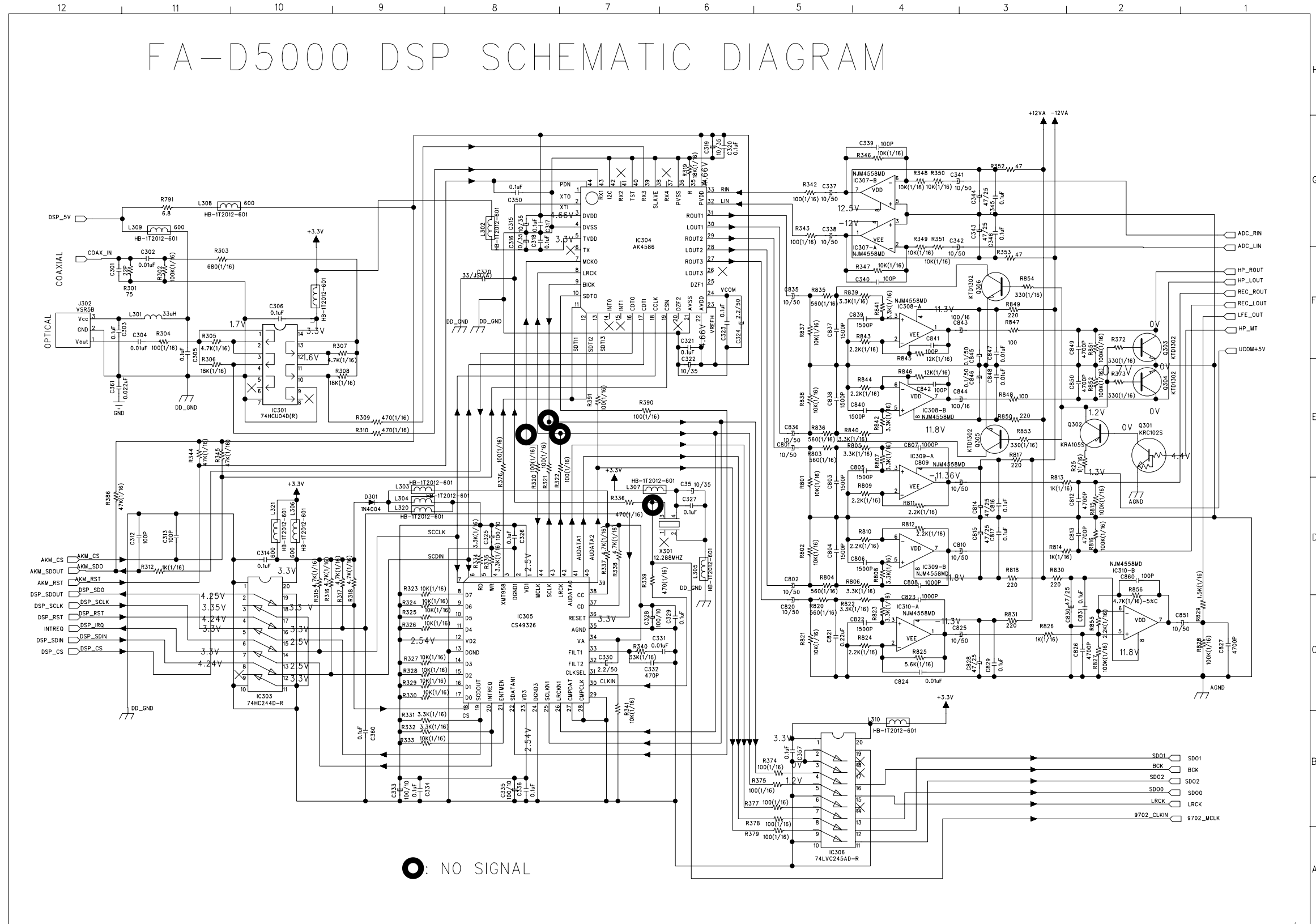
• FRONT SCHEMETIC DIAGRAM



• MAIN (PRE, μ-COM) SCHEMATIC DIAGRAM

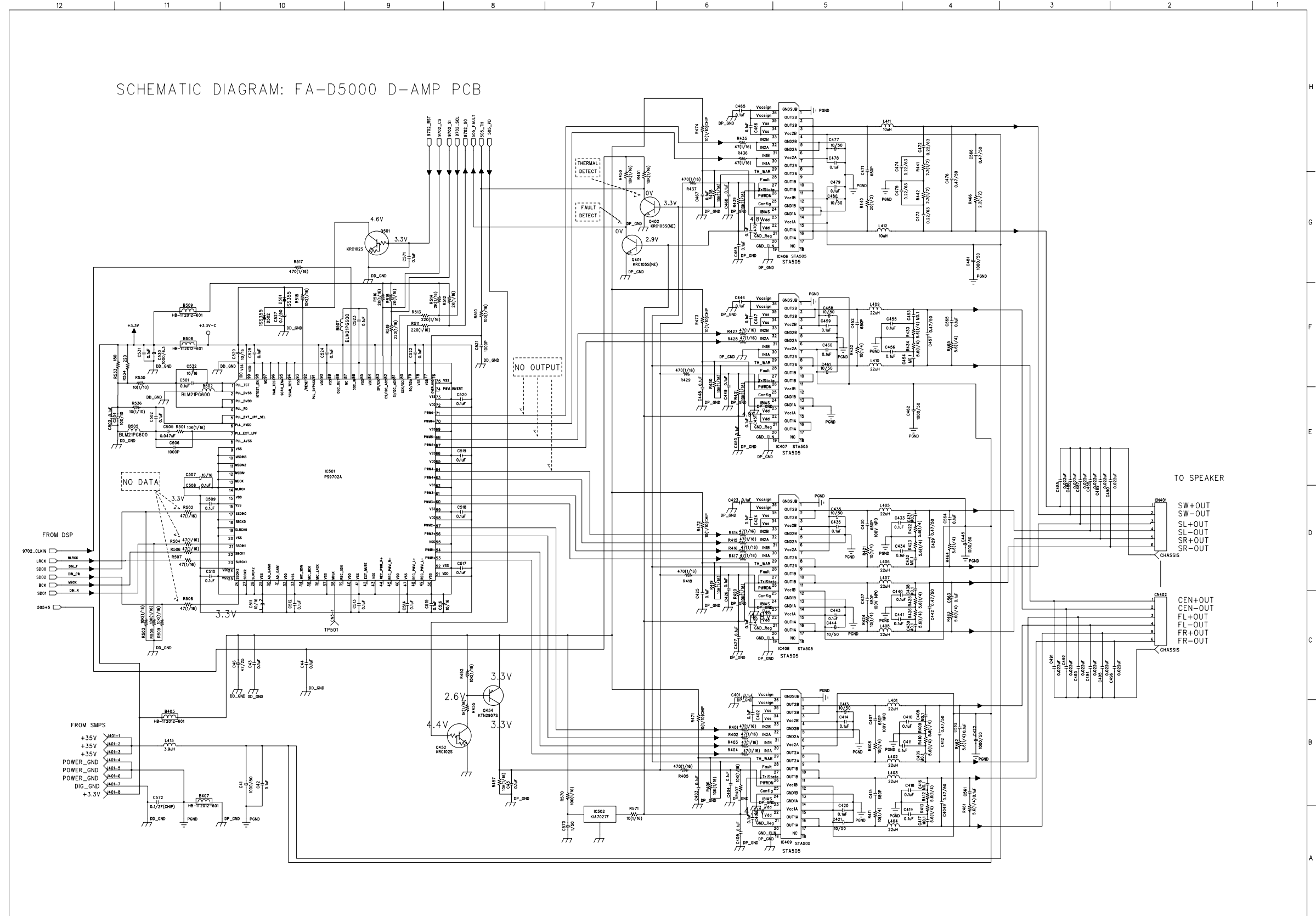


• DSP SCHEMATIC DIAGRAM

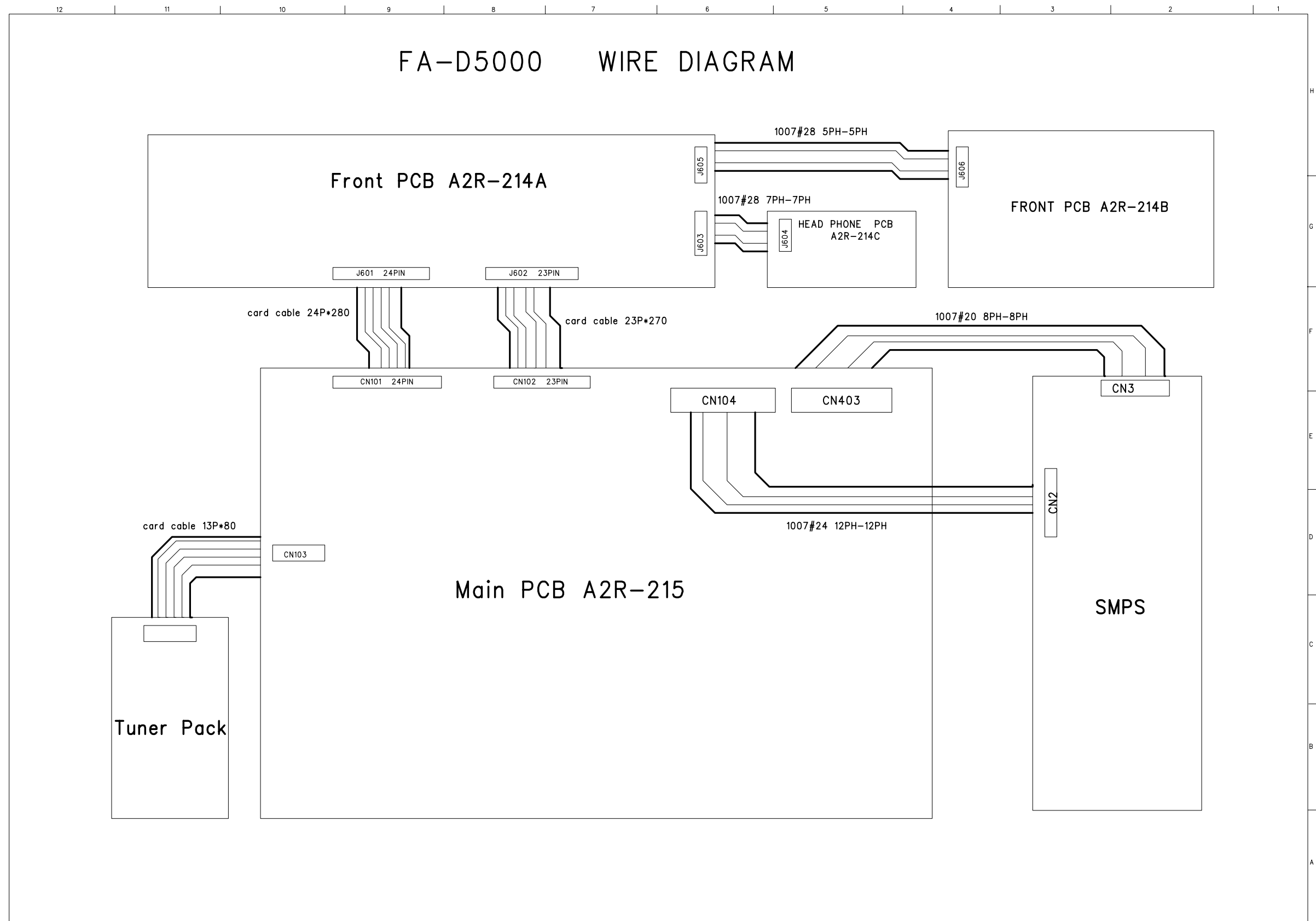


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• AMP SCHEMATIC DIAGRAM

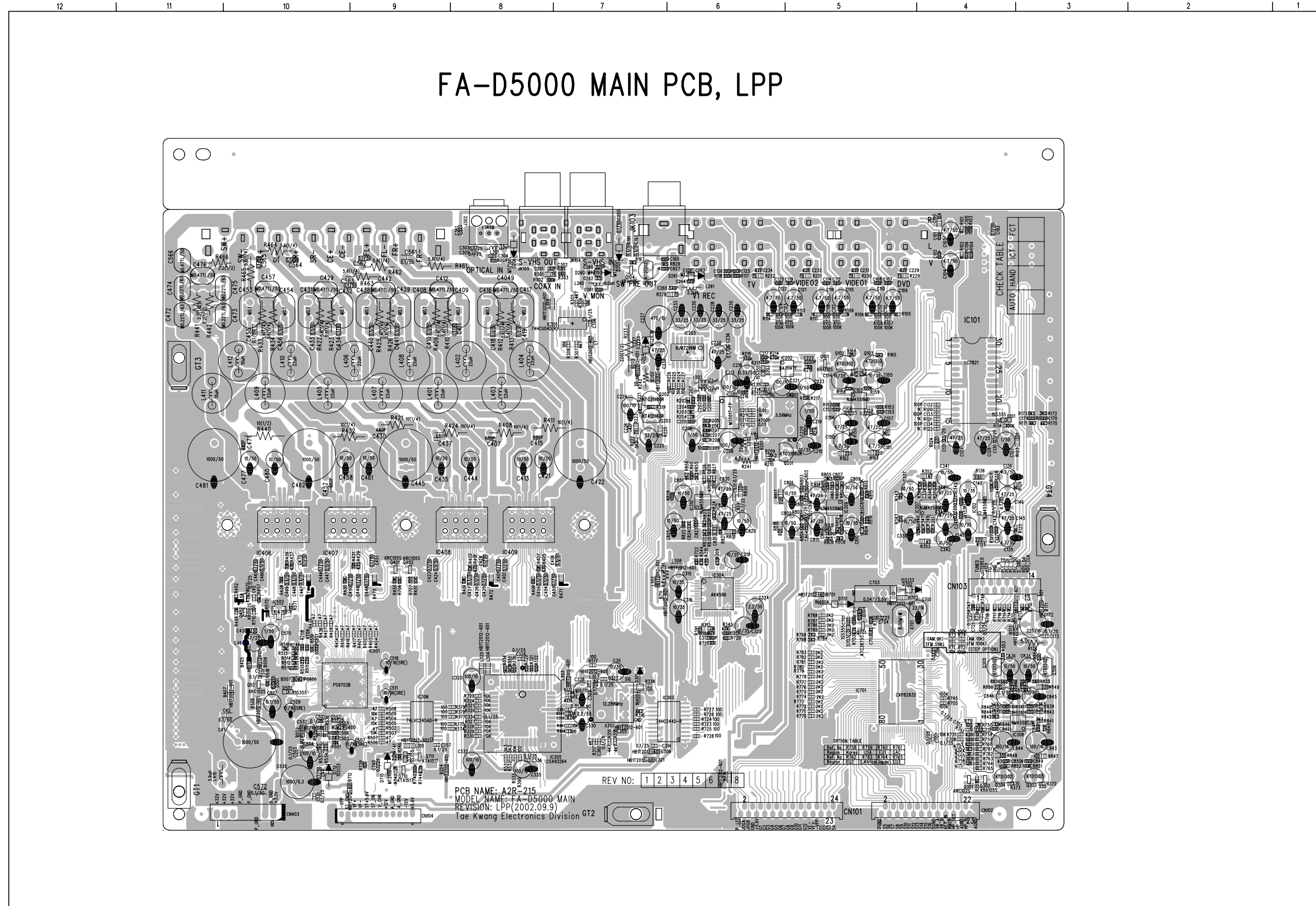


WIRING DIAGRAM

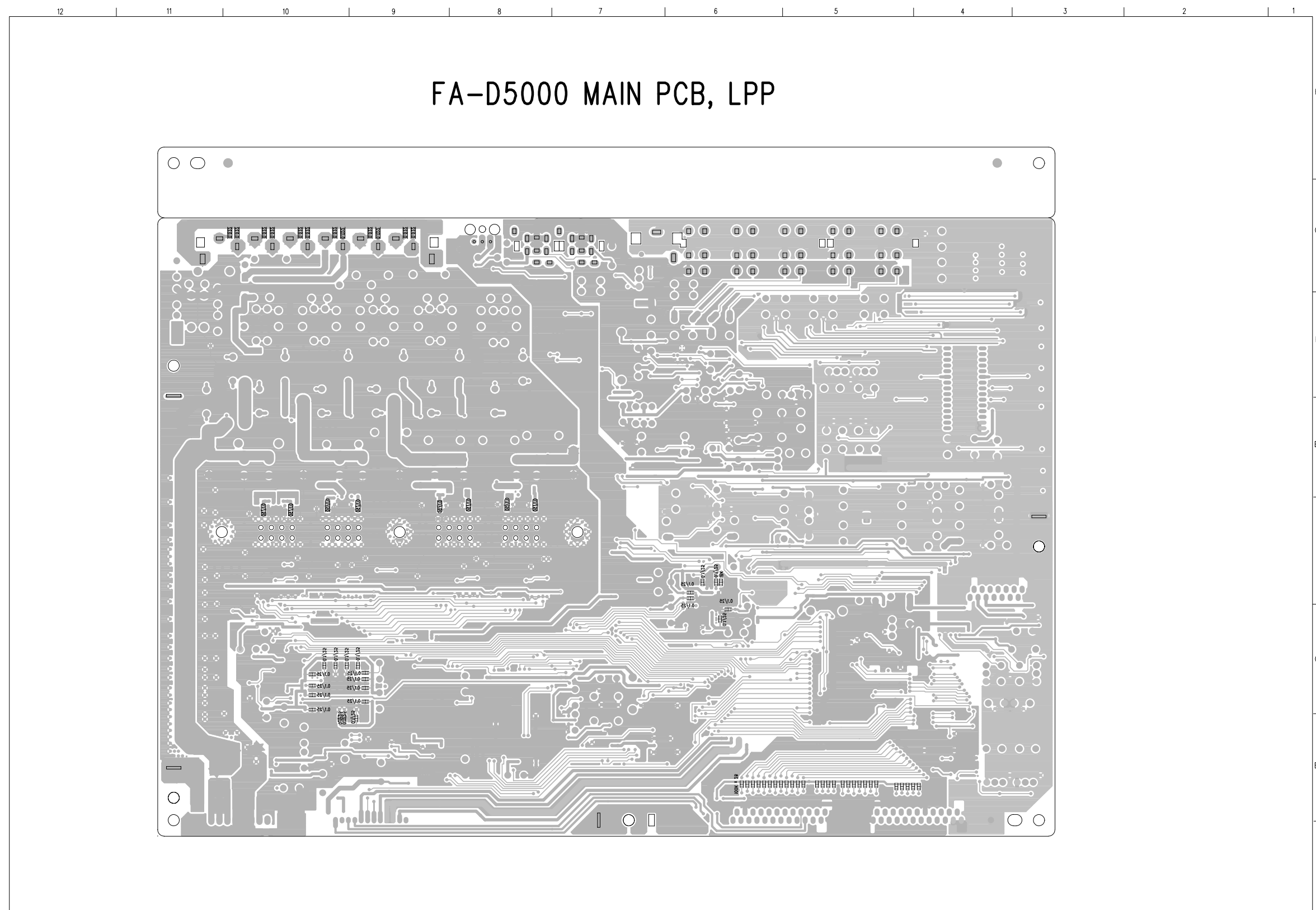


PRINTED CIRCUIT DIAGRAMS

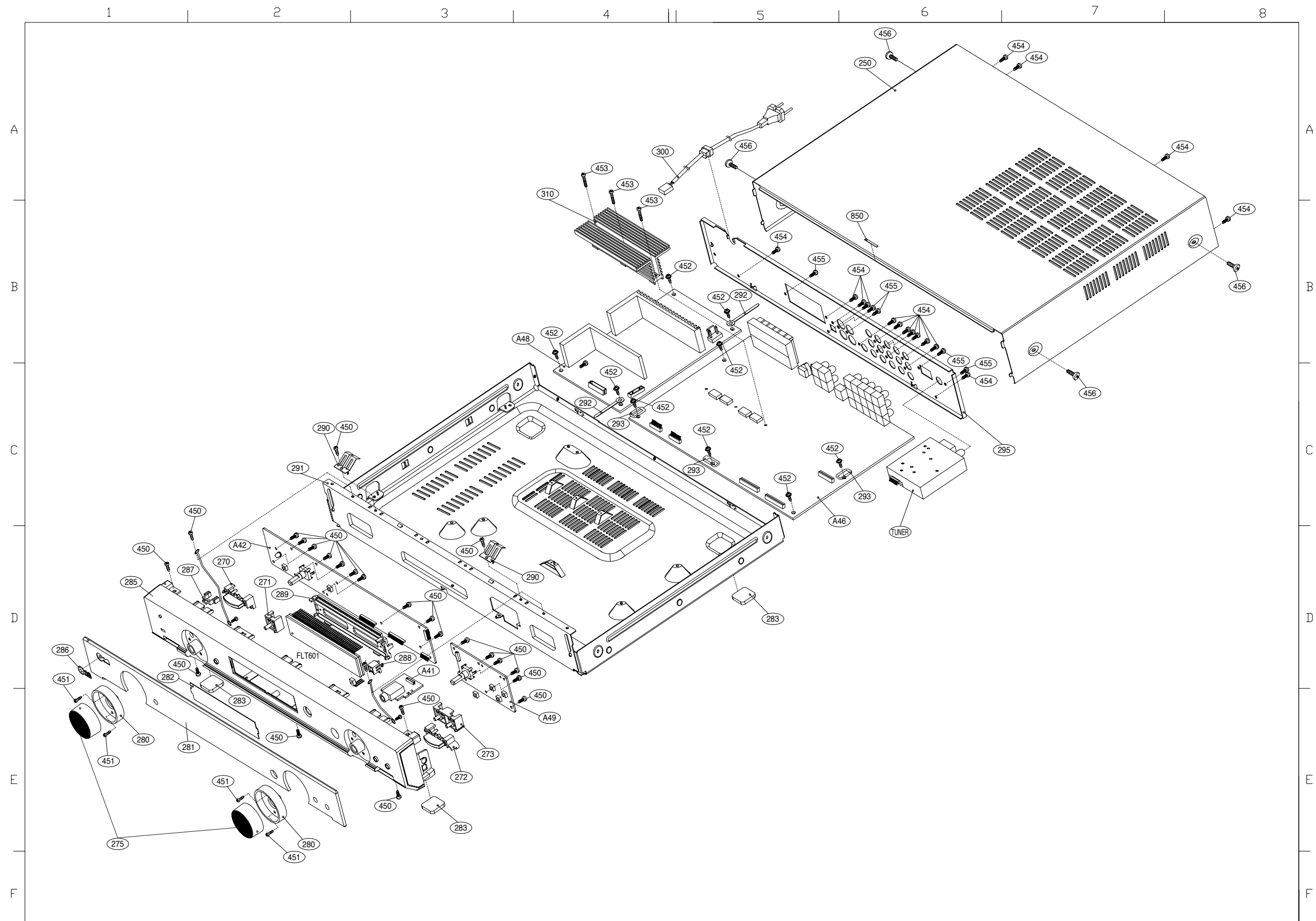
1. MAIN P.C.BOARD (COMPONENT SIDE)



1. MAIN P.C.BOARD (BOTTOM SIDE)



SECTION 3. EXPLODED VIEWS



TKG-05-57 (REV.2 95/09/13)